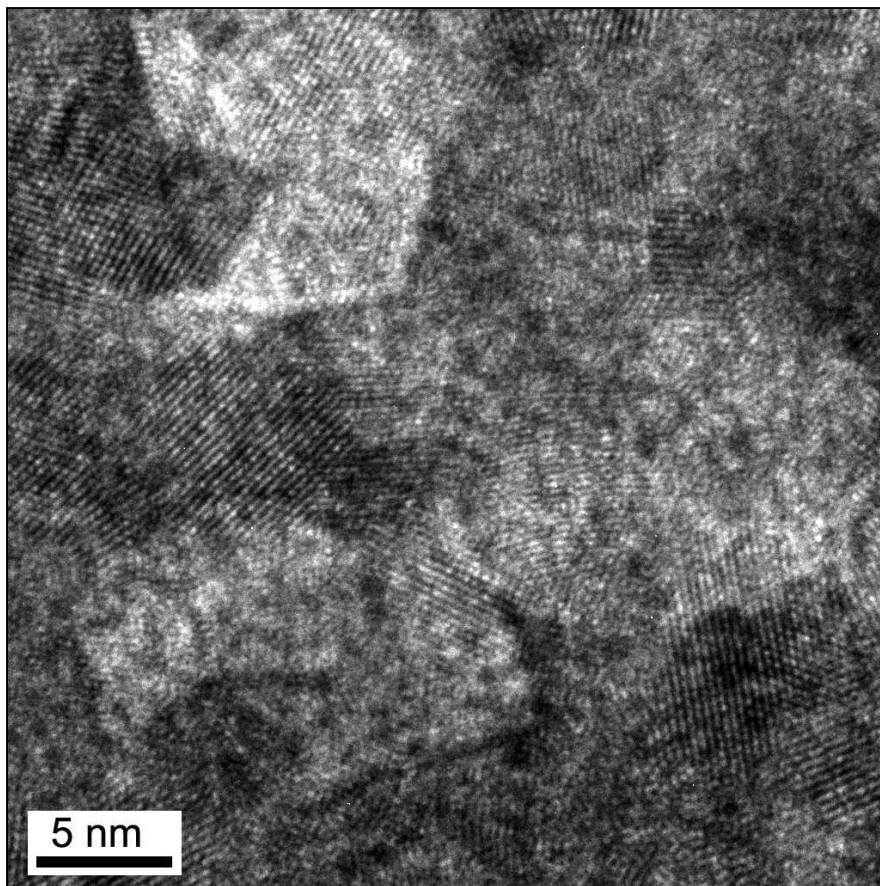




A brief introduction to TEM



**Chad Parish
Luke Brewer**

**Materials Science
and Engineering**

**Sandia National
Laboratories**

For more information

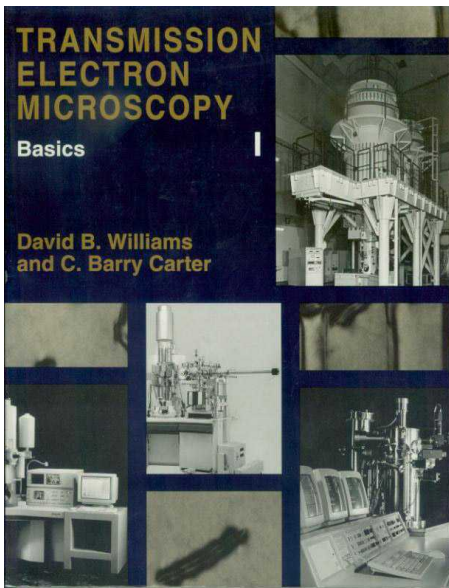
TEM has been around since the 1940s – there's plenty to read if you want more information

Most recent choices:

Williams & Carter, 1996:

**Best general
introduction**

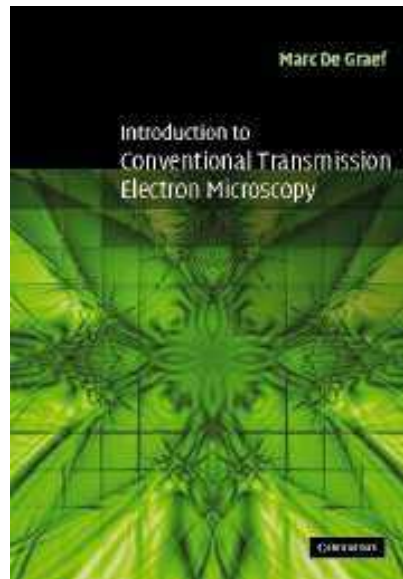
Diffraction, imaging,
chemical microanalysis



De Graef, 2003:

**Mathematical and
computational**

Imaging and diffraction



Classic references:

Williams, Introduction to Analytical Electron Microscopy, 1984; Goldstein et al., Principles of Analytical Electron Microscopy, 1986: both cover chemical microanalysis. Somewhat out of date, but still valuable.

Hirsch et al., Electron Microscopy of Thin Crystals, 1965: Theory of imaging from the people who invented it.

Journals to watch:

Microscopy and Microanalysis, Ultramicroscopy, Journal of Microscopy, Journal of Electron Microscopy, Journal of Applied Physics, Applied Physics Letters, and others

Why do TEM?

- **Ability to directly visualize the structures of materials down to the atomic scale**
- **Ability to measure crystallographic parameters down to nanometer scales**
- **Sensitivity to crystallographic defects**
 - Dislocations (original use of TEM in materials science)
 - Grain boundaries/phase boundaries
 - Twins
- **Measure and Map elemental composition down to atomic scales**
 - EDS
 - EELS
- *Ability to combine all of these measurements...*
 - In one instrument!*
 - On one sample!*
 - In one area!*

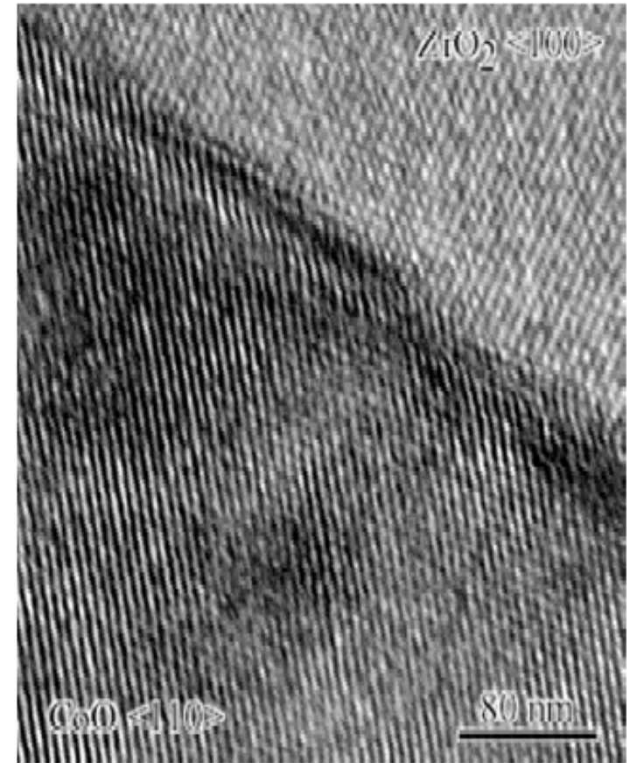


FIG. 4. HREM lattice image of CoO/ZrO₂ showing atomic-level abruptness between phases without the presence of a tertiary phase.

J. Mater. Res., Vol. 17, No. 4, Apr 2002

Why shouldn't we do TEM?

- Can a suitable sample be found?
Difficulty in sample preparation—need thin (<200 nm) samples
Stable
Representative
- Could we get the information by an easier/faster means?
Powder XRD or EBSD
X-ray fluorescence or microprobe
AFM or SEM
- Will there be difficulty in interpretation of the results?
TEM is a 2D projection of a 3D reality!
Data (images, spectra) can be susceptible to artifacts
- Cost?
TEM cannot be done in ½ hr
TEMs are expensive instruments (\$750K--\$4M)

What is a TEM?

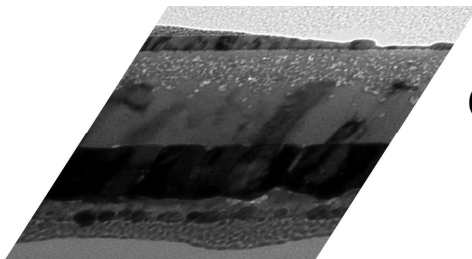
Conceptually:

Illumination stage:
Produces a bright
electron beam

Electron beam

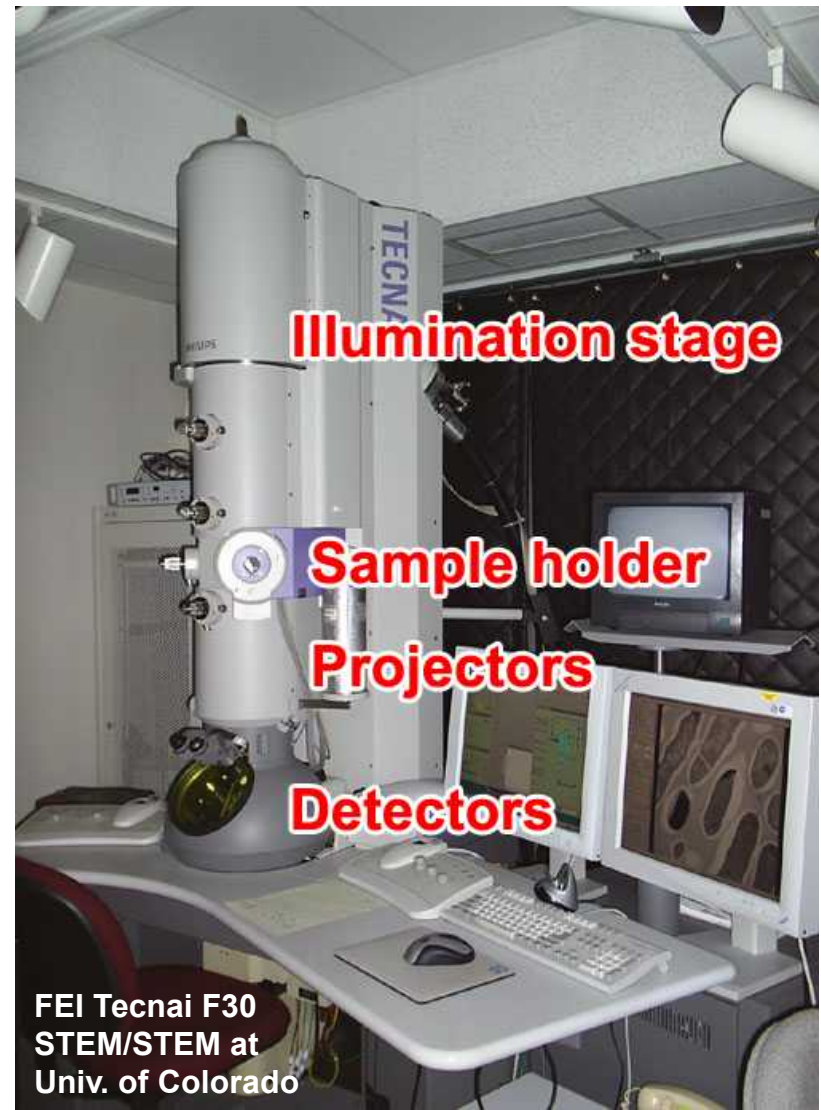
Thin sample (<200 nm)

Projector stage:
Sends electron beam to
the detectors



Detectors:
CCD camera,
fluorescent
screen, etc.

Practically:



FEI Tecnai F30
STEM/STEM at
Univ. of Colorado

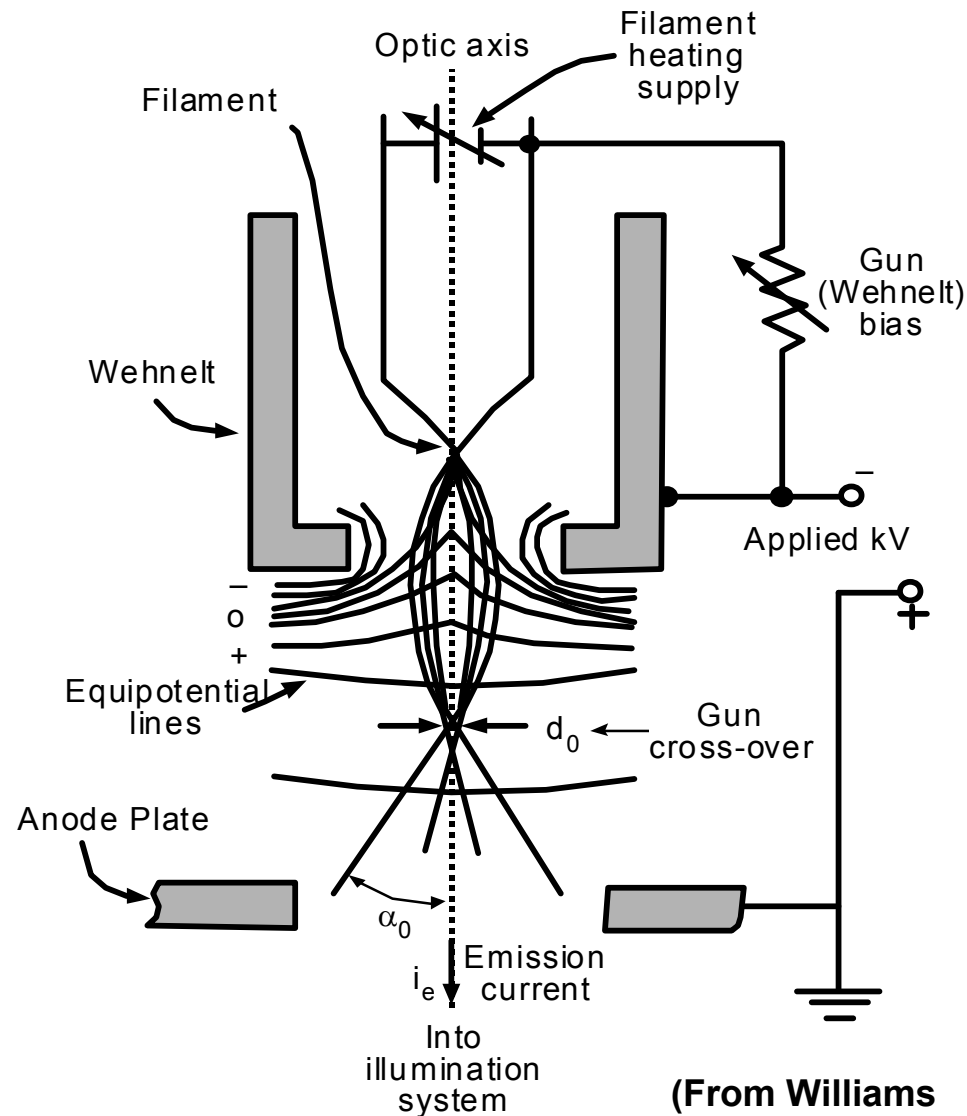
First thing: we need high-energy electrons

There are several types of electron guns

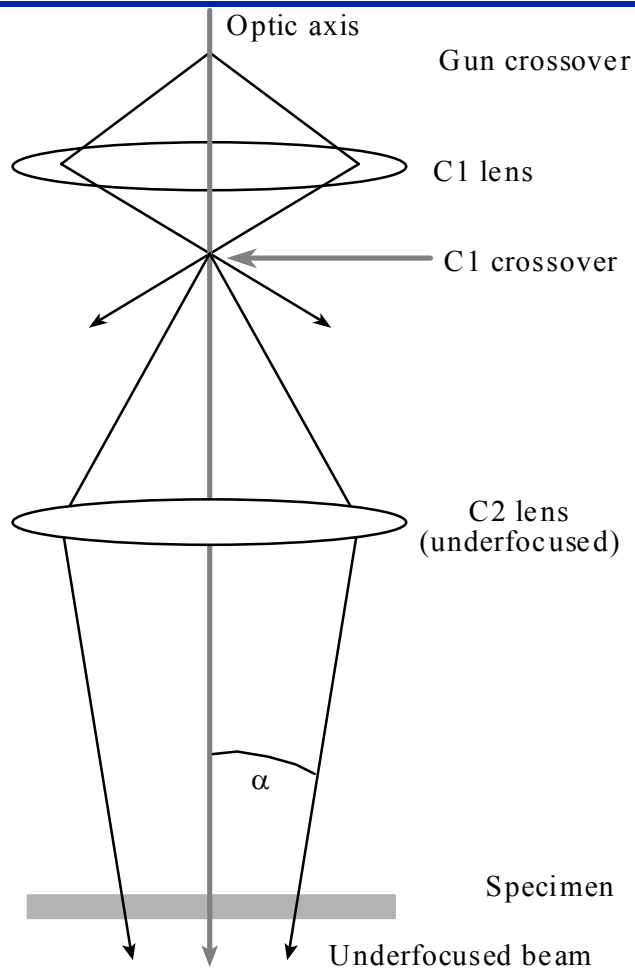
Example: thermionic electron source

A filament (W or LaB_6) is heated white-hot, which allows electrons to escape
→ similar to a lightbulb

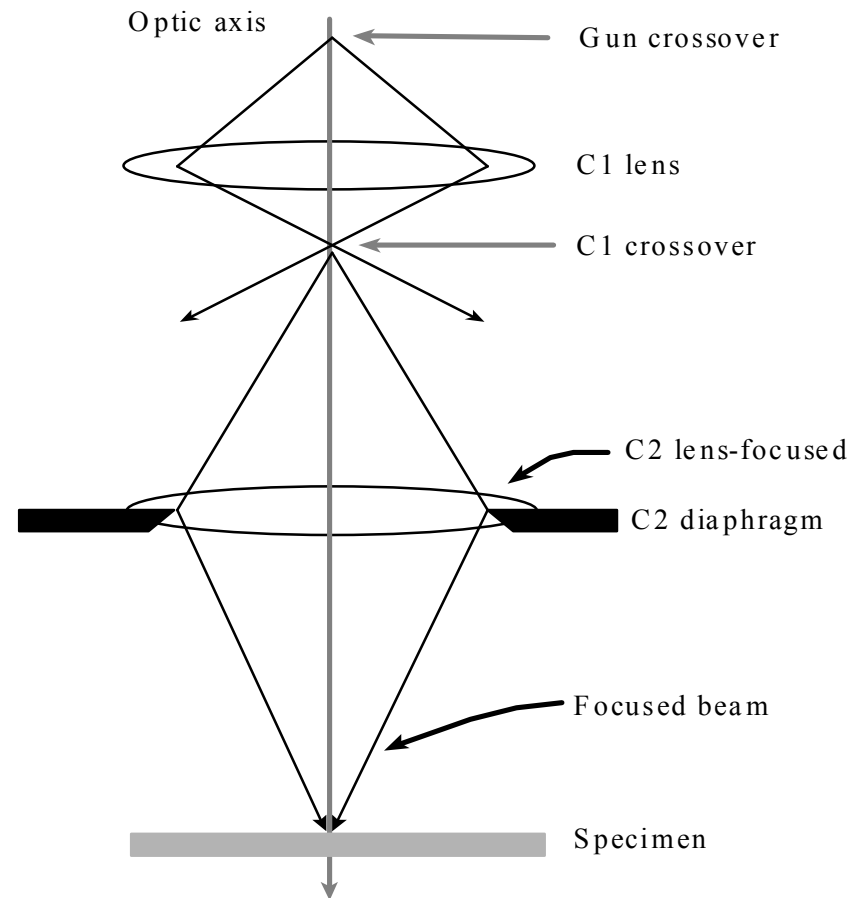
The filament assembly is floated at high voltage (80-300 kV) to accelerate the electrons



Next: we must illuminate the sample



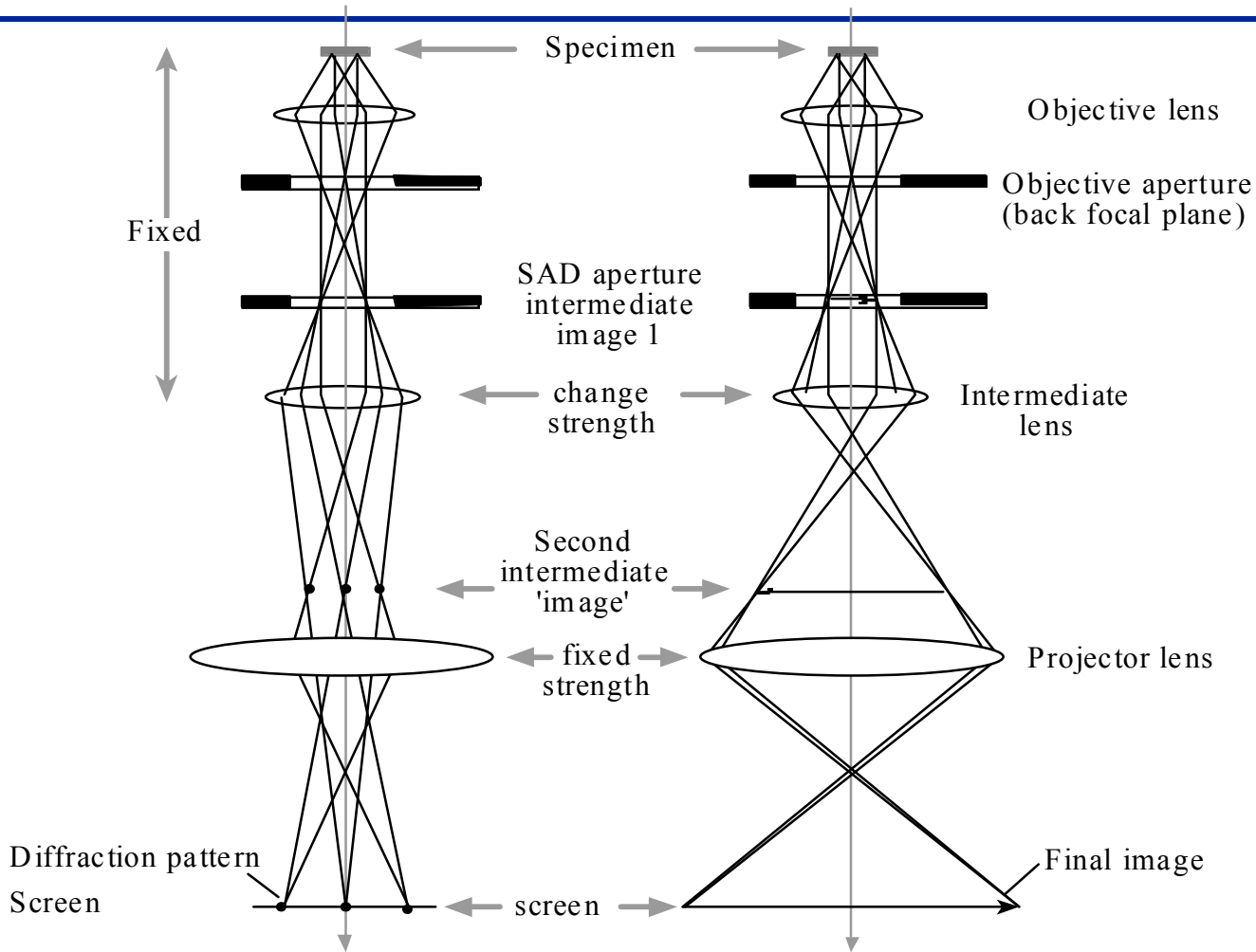
Imaging: nearly-parallel beam



Chemical microanalysis: focused beam

(From Williams
and Carter)

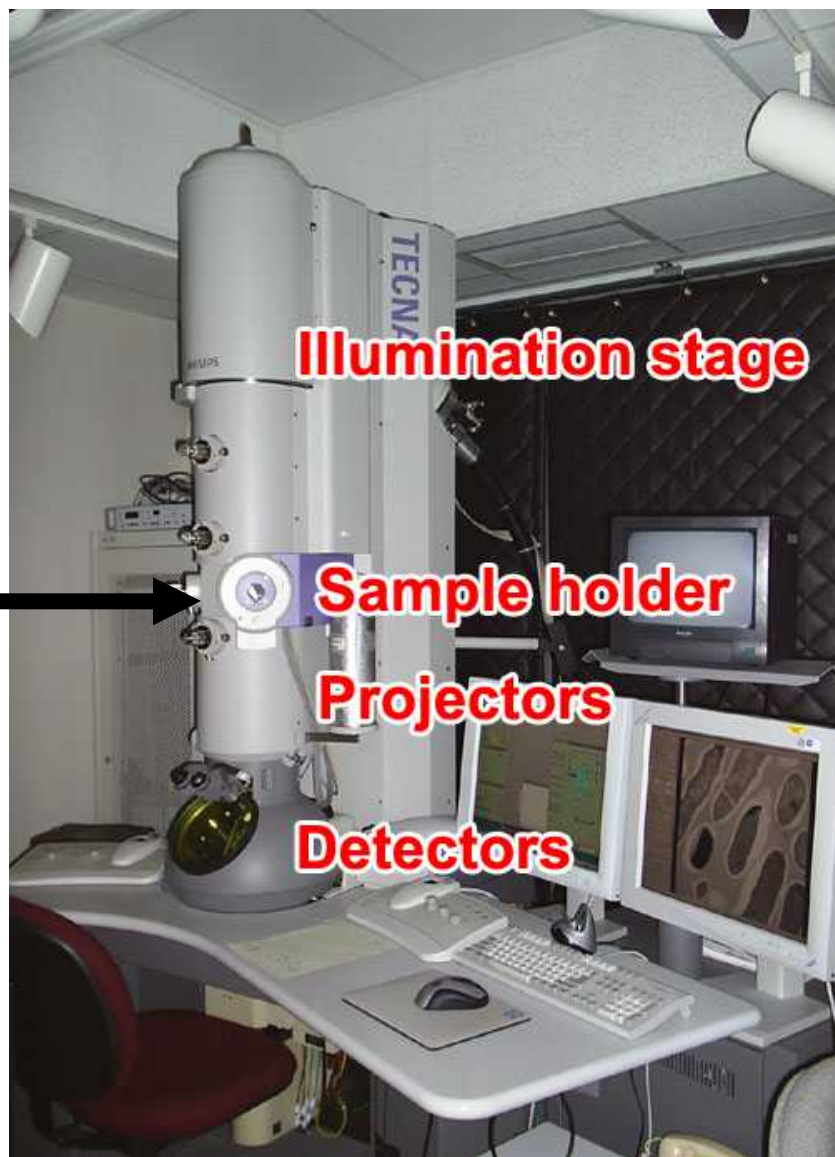
We then project the image onto the detector



(From Williams and Carter)

Limiting factor: the objective lens

Sample + holder
enters from the
side

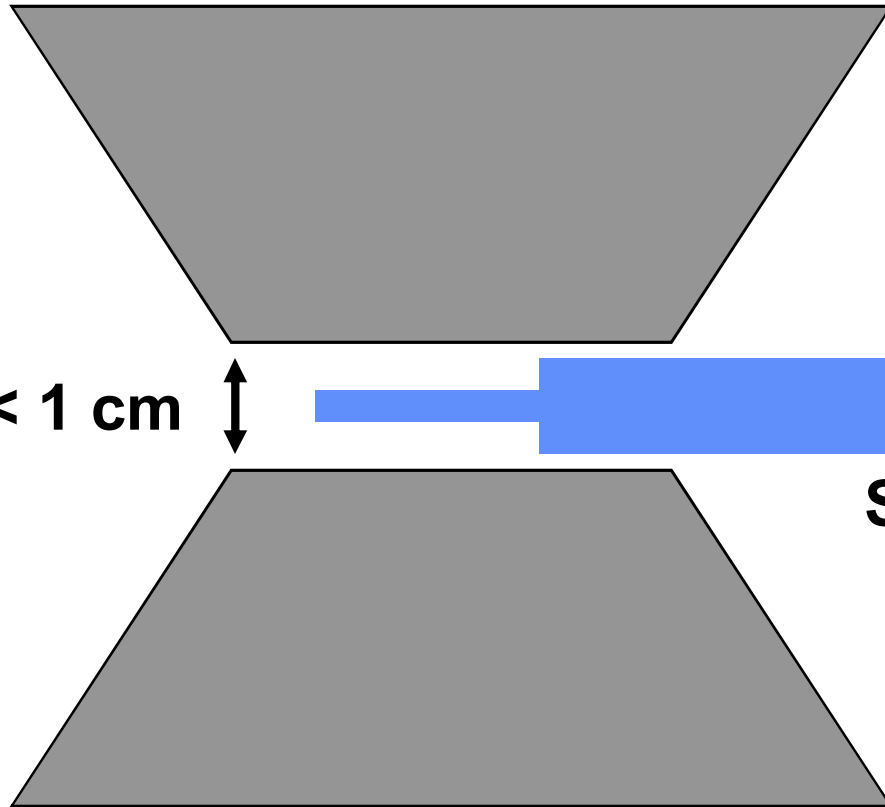


Limiting factor: the objective lens

Objective lens:

**Two electromagnets
made from
thousands of turns
of copper wire**

Pole piece gap < 1 cm



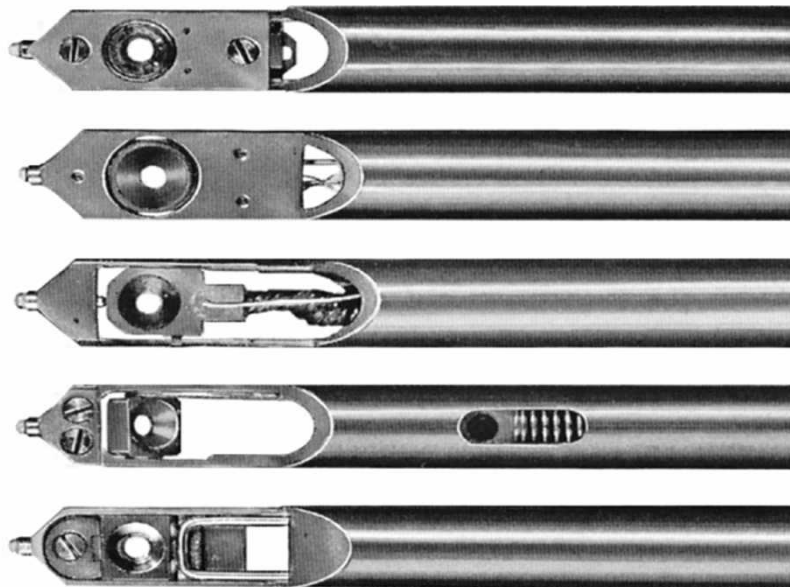
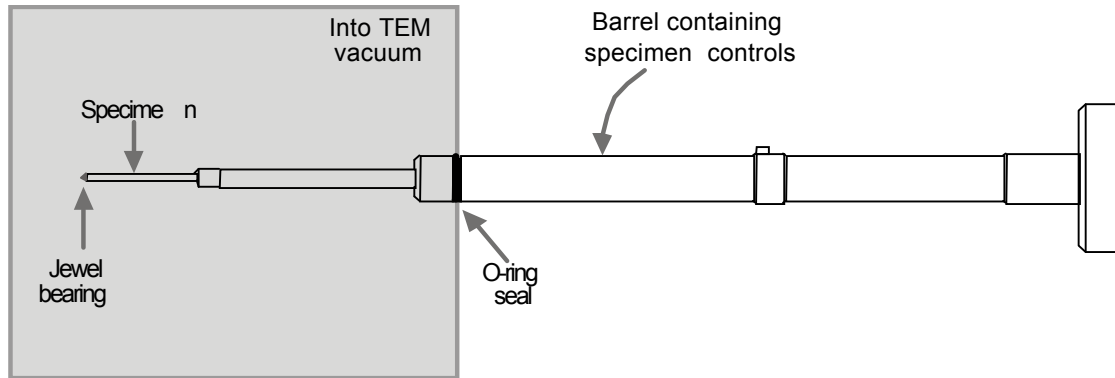
**Side-entry
sample
holder**

**Smaller gap → better lensing → image smaller features
2-3 cm (1960s) → 3-4 mm (today)**



**Sandia
National
Laboratories**

Limiting factor: the objective lens



↔
≈ 1 cm

(From Williams
and Carter)

Sample preparation

The small amount of space inside the objective lens limits our sample preparation

Standard sample size for all TEMs: 3mm diameter

How can we make 3mm samples of our materials?



Sample preparation

- **Thin**

- Less than 200 nm preferable, less than 50 nm for good HREM/EELS

- Good news—nano particles are inherently thin

- **High energy electron beam can cause**

- Damage (radiolysis, knock-on)

- Crystallization

- Evaporation

- **Clean**

- Free of hydrocarbons on surface

- Oxidation of surface on some metals can be problematic

- **Representative of the bulk** (A key question for any microscopy technique)

- Not so much of a problem for nano particles

- Very important for dislocation studies in metals—did we relax the material?

- You don't want the “one representative area”!



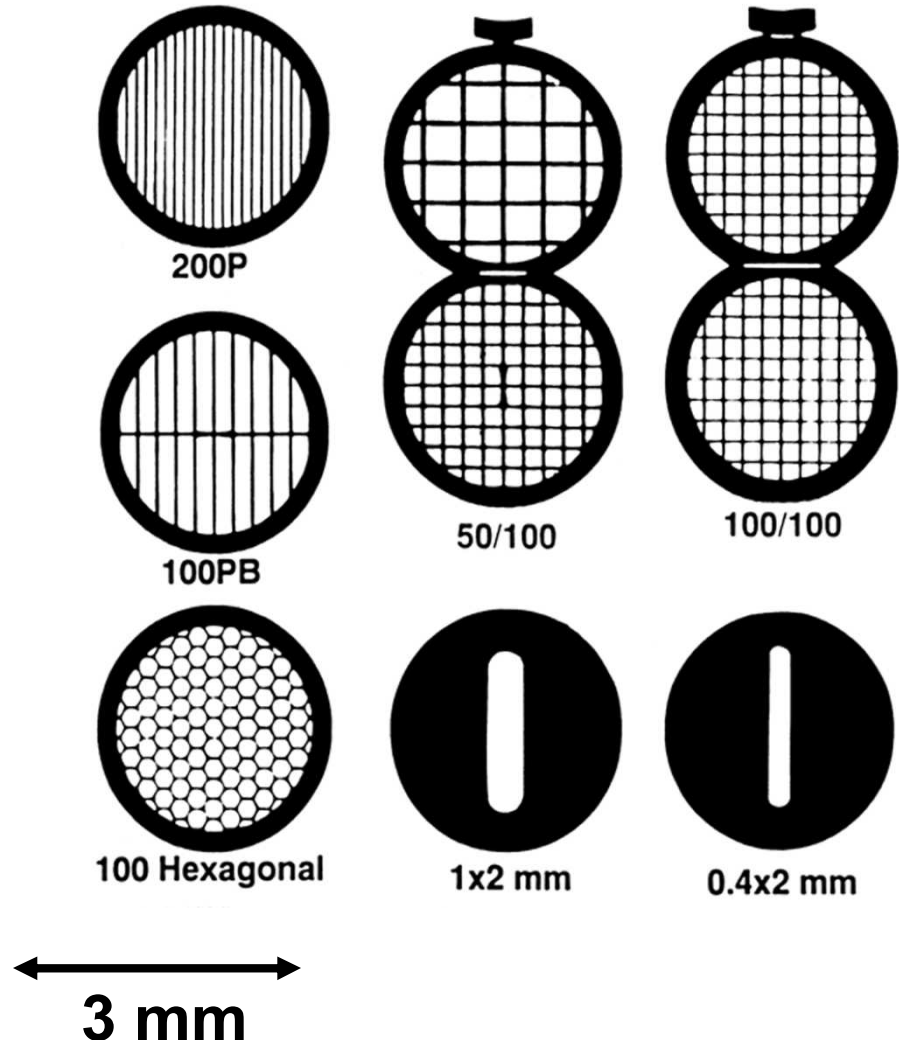
How to hold your sample (particularly nanoparticles)

Common Grid Materials:
Cu Ni Pt Be C Au

Most has a very thin layer of amorphous carbon over a metal mesh

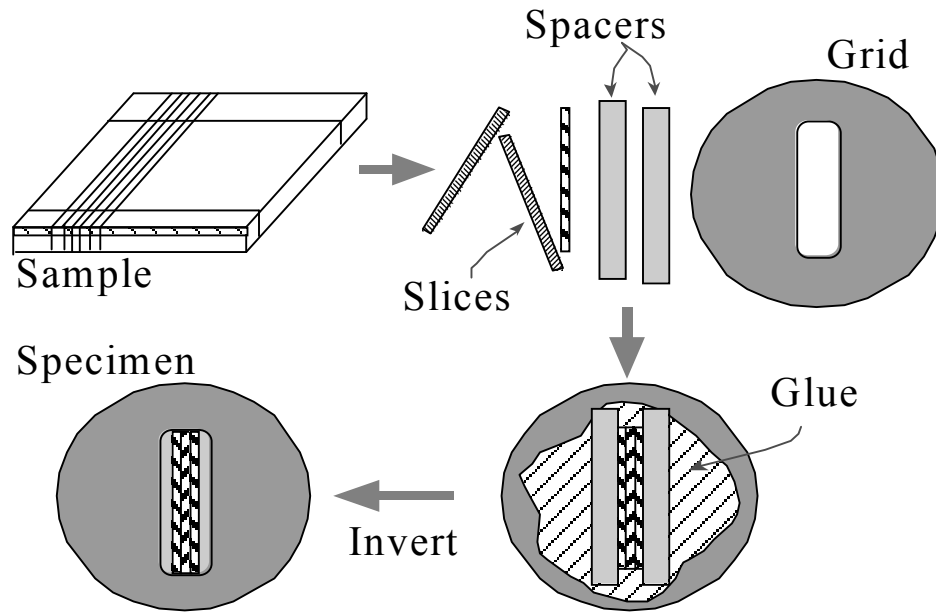
Can have either a continuous film or “holey” carbon

Samples can be prepared by suspending sample in volatile solvent (isopropanol, methanol, etc.) and depositing a small amount on the grid



(From Williams and Carter)

Thinning a bulk sample: cutting and mounting



This process used to be the primary means of preparing thin film TEM samples

A grid is used to provide mechanical stability

Quality of glue joints is particularly key

This process takes a lot of practice—dreaded by grad students everywhere!

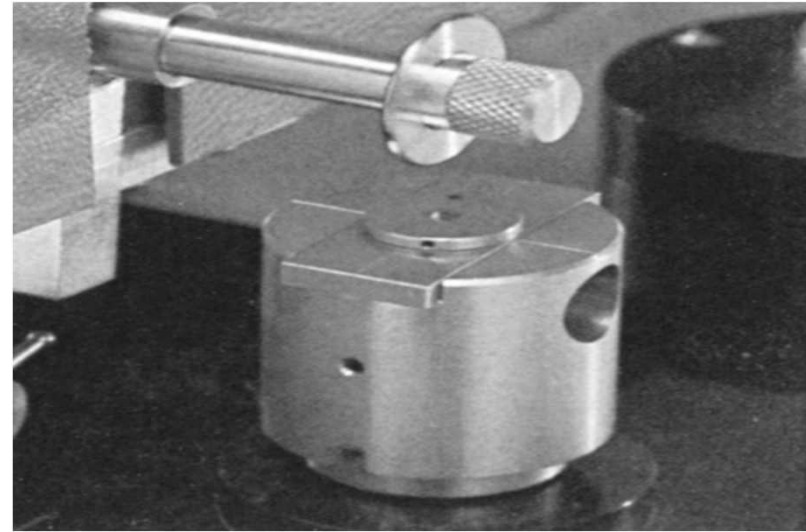
(From Williams
and Carter)

Thinning a bulk sample: dimpling

Small wheel rotates on top of solid, polished specimen using abrasive (Si_3N_4 or diamond) slurry

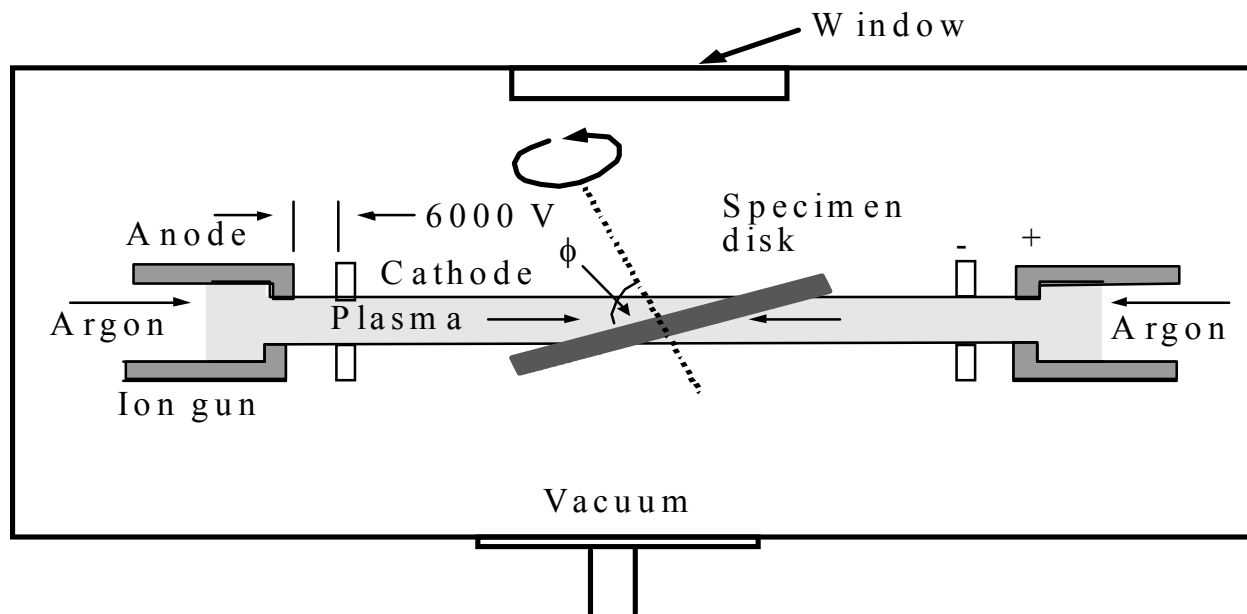
Creates a dimple in the surface of the sample

The result is a sample which is 100 μm thick at the edges and <10 μm thick at the center



(From Williams
and Carter)

Thinning a bulk sample: ion milling



(From Williams and Carter)

Most samples not electron transparent after dimpling

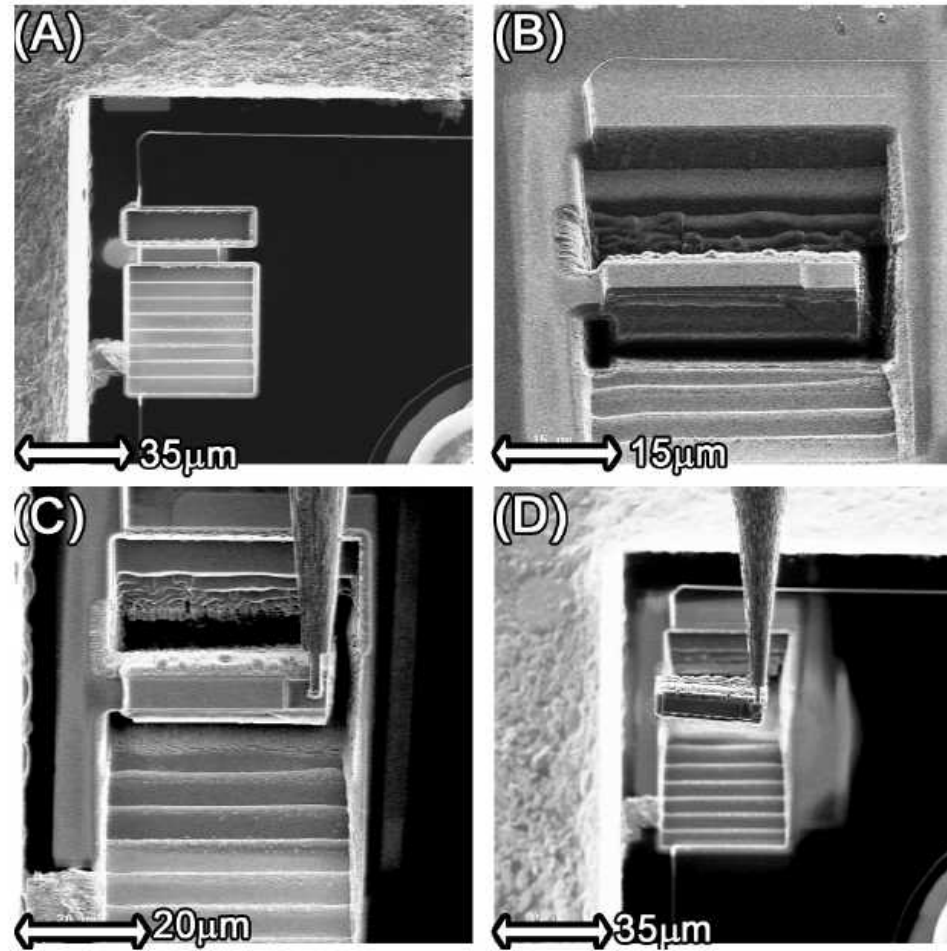
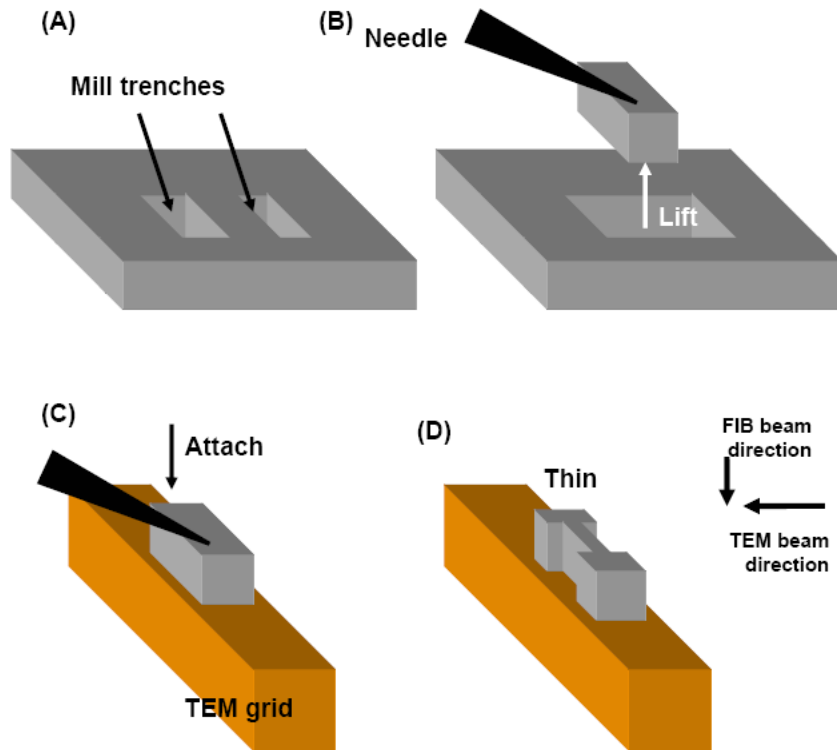
Ion milling takes sample from thin ($\sim 10\ \mu\text{m}$) down to electron transparent ($< 200\ \text{nm}$)

Need to be careful about not damaging the sample (Ar implantation, specimen heating, etc.)



Sandia
National
Laboratories

The newest technique: focused ion beam milling



Sample thinness: main historical problem

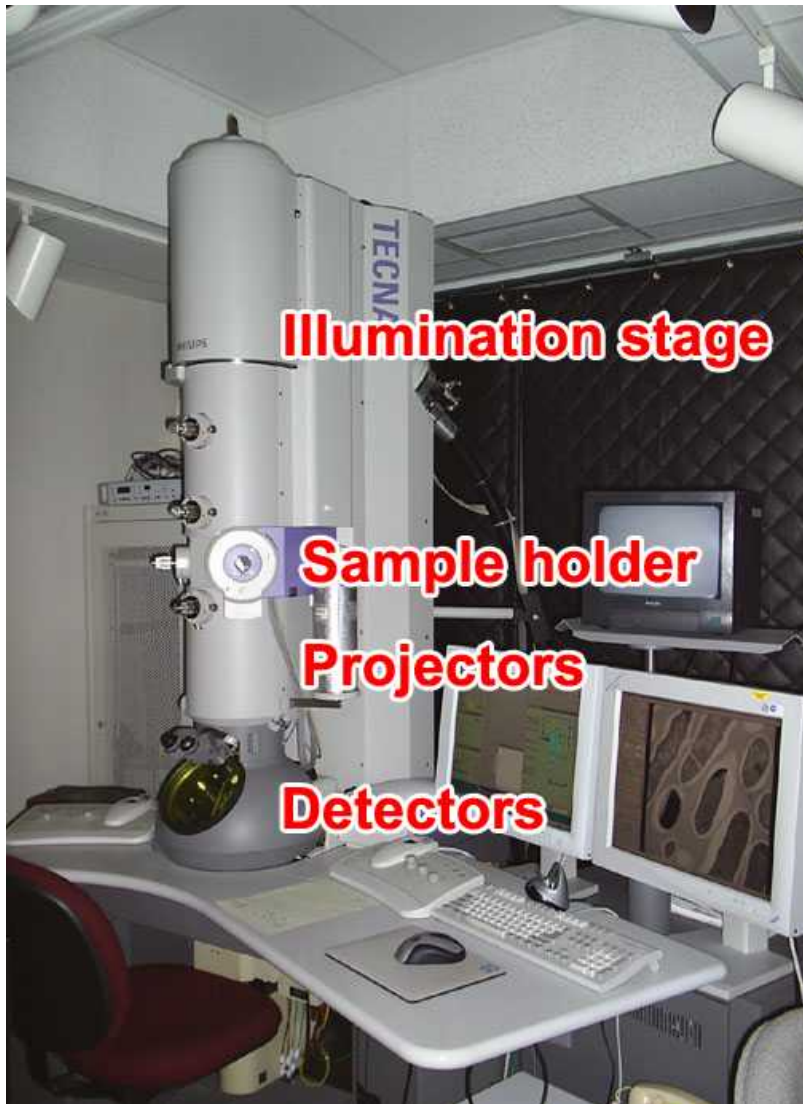
Until about 1970, few samples could be made <200 nm thick

The trend was toward higher-energy microscopes (1-3 MeV beam energy) to penetrate thick samples

Example: US Steel's million volt microscope (1960s)

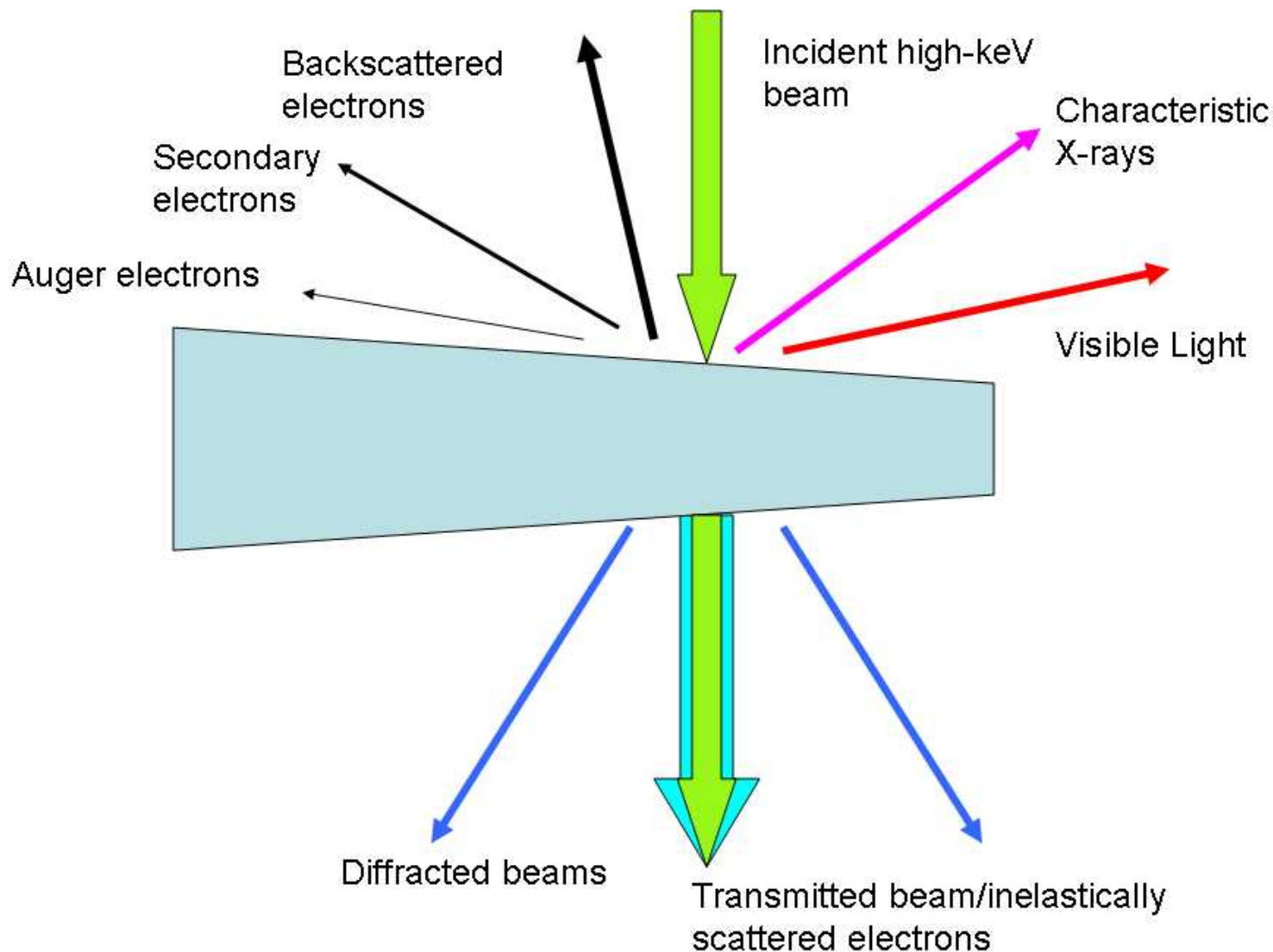
With the invention of the ion mill & other tools, TEM voltages dropped to the 80-300 keV seen today

Recap: what we've said so far



1. Electron gun + high voltage generate an electron beam
2. The illumination stage transfers this beam onto the sample
3. The sample is held in a side-entry holder
 - Sample must be thin
 - Sample + holder must fit into a small gap
4. Projector lenses take the transmitted electrons and send them to the detector

What signals do we have to work with?



Electron diffraction in TEM

$$\lambda = \frac{2d}{n} \sin(\theta)$$

Electrons, just like x-rays and neutrons, are readily diffracted

Kinematic theory (Bragg's law) predicts peak positions

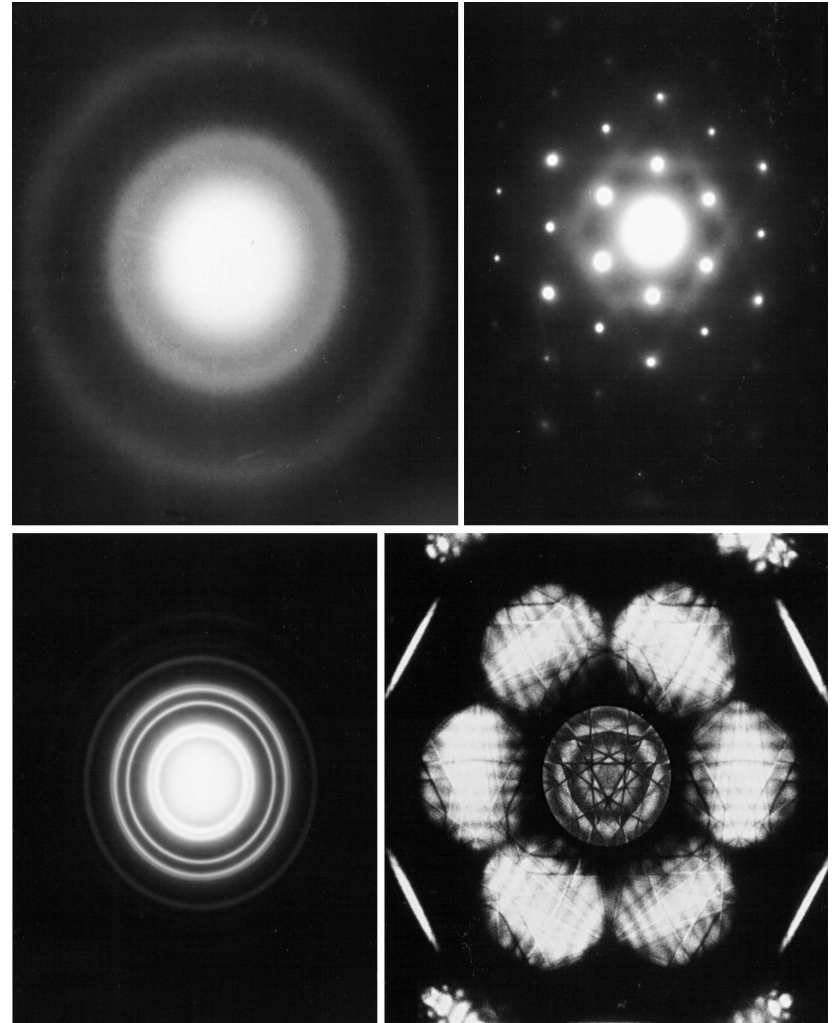
Intensities require dynamical theory → terrifying mathematics

A great deal of information is available with more advanced electron diffraction (CBED, etc.)

Space-group analysis

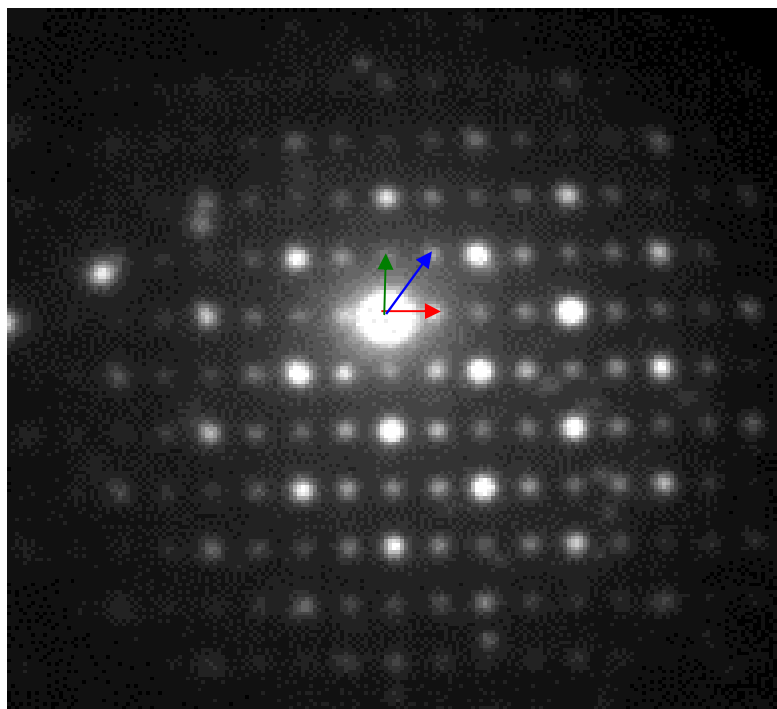
Superlattice ordering

Elastic strain measurement



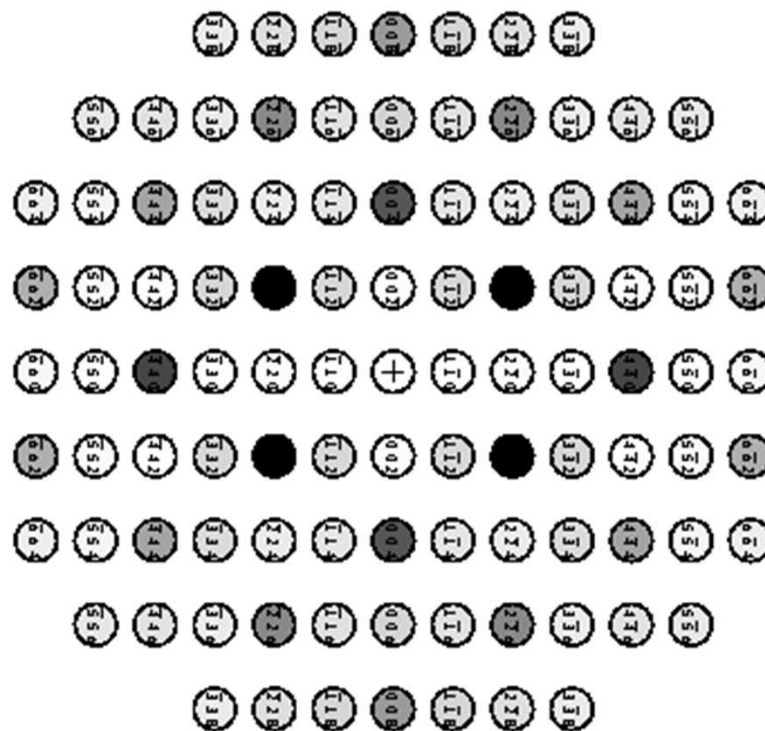
(From Williams and Carter)

Selected Area Diffraction Patterns -- Er_2O_3 particle



$\langle 110 \rangle$ zone axis

$g_1 : (0, 0, 1) / g_2 : (1, -1, 0) / g_3 : (0, 1, 0)$
 Zone axis : $[1, 1, 0] / \text{Foil normal} : [1, 1, 0]$



Measured $d_{011} = 7.2\text{\AA}$ (7.45 \AA)

Measured $d_{200} = 5.19\text{\AA}$ (5.27 \AA)

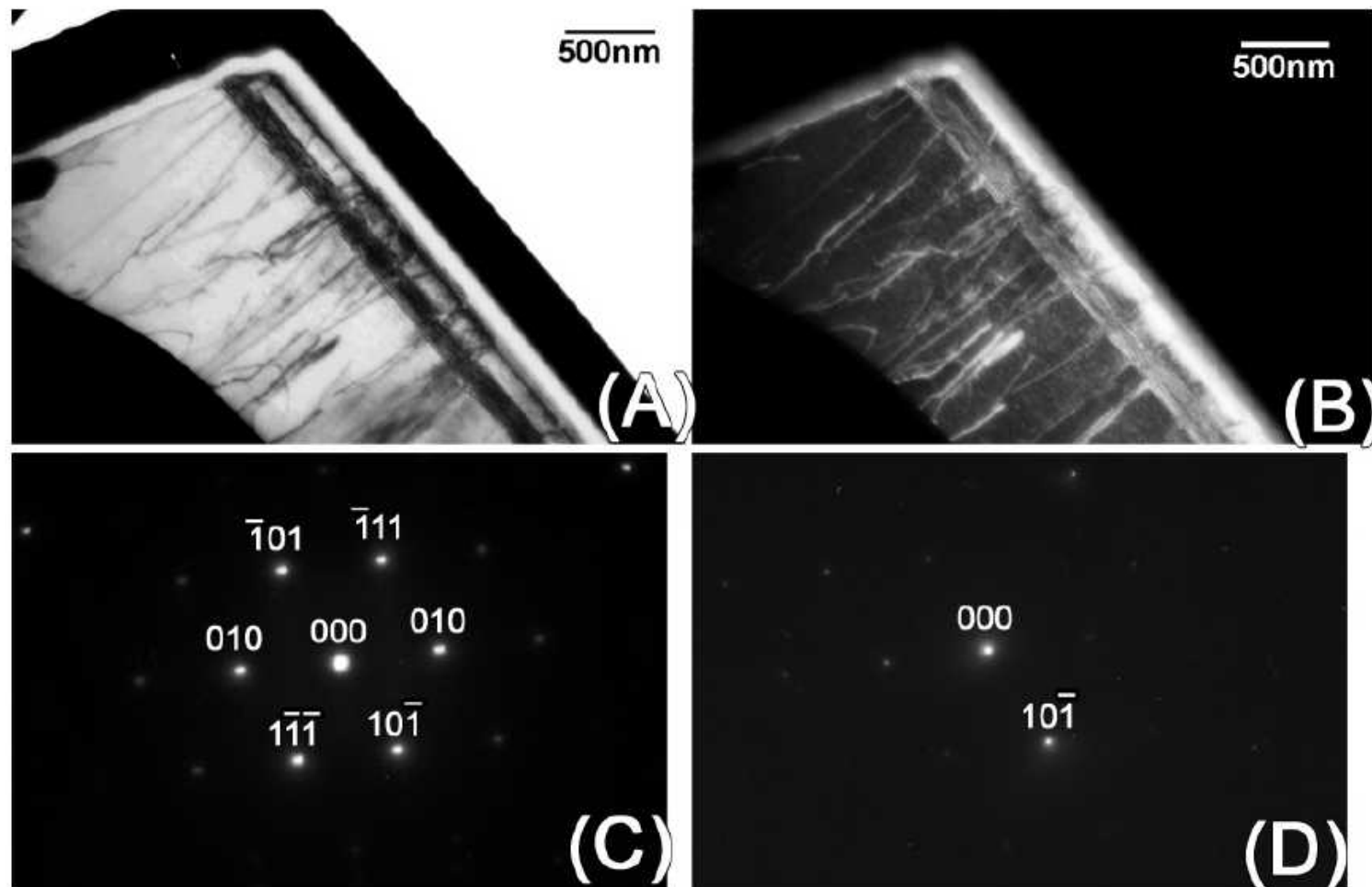
Measured $d_{211} = 4.14\text{\AA}$ (4.30 \AA)

Measured Ratio $R_{200}/R_{011} = 1.39(1.41)$

Measured Ratio $R_{211}/R_{011} = 1.74(1.73)$

All values in parentheses represent calculated values.

Conventional TEM imaging – ideal for crystallographic defects



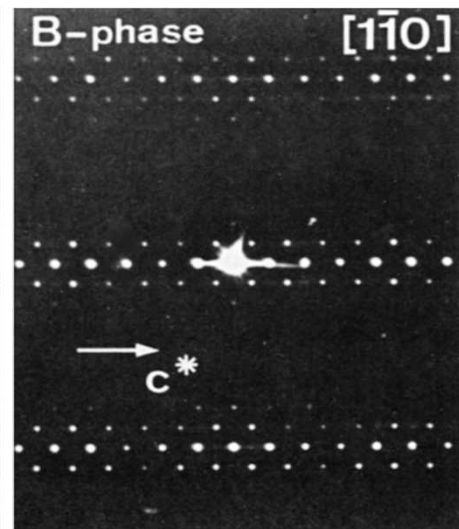
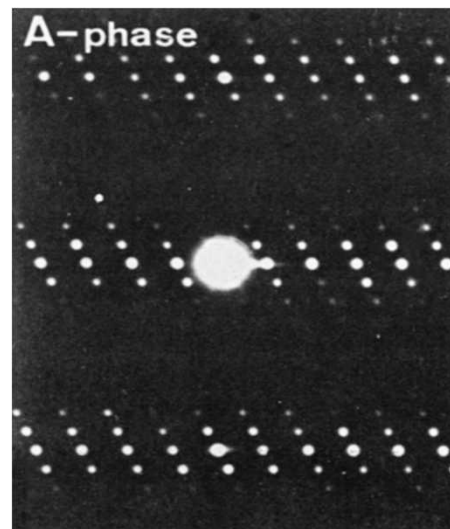
High Resolution Electron Microscopy (lattice imaging)

If we form an image using multiple diffraction spots, we get a very useful interference pattern—an HREM lattice image

Lattice images can be used to confirm crystallinity of an area

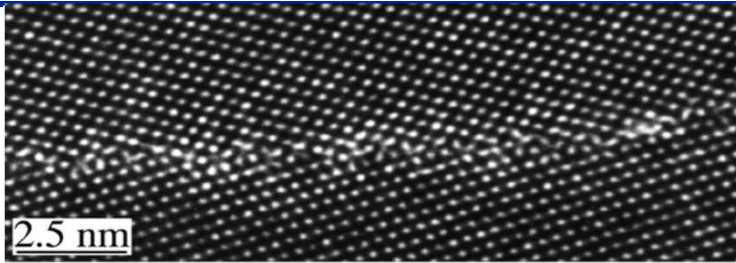
With careful calibration, can be used to measure d-spacings and look for defects (e.g. misfit dislocations)

Quantitative structural determination from HREM images requires detailed modeling

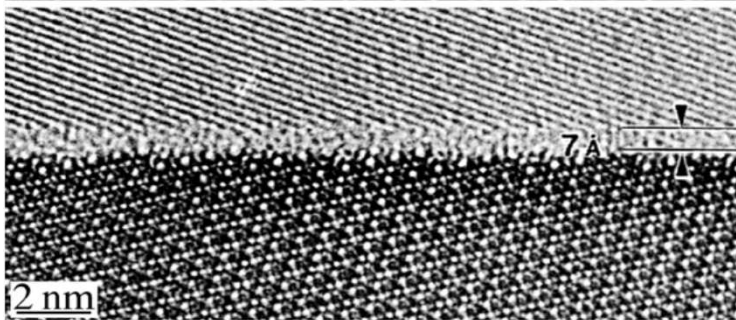


(From Williams and Carter)

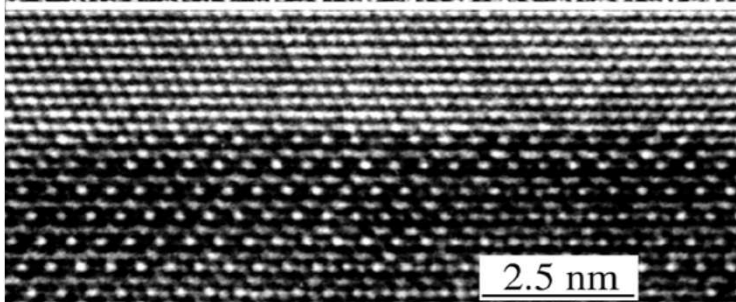
Examples of HREM images



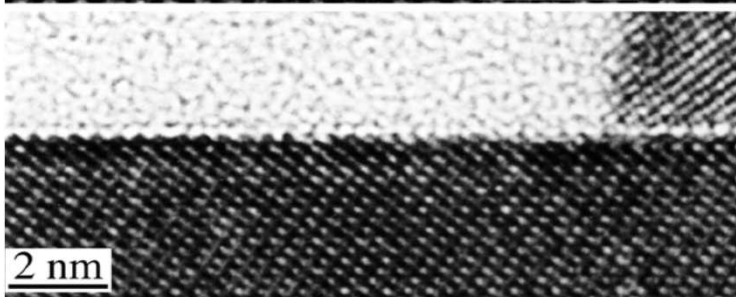
Ge



Si₃N₄



NiO/spinel

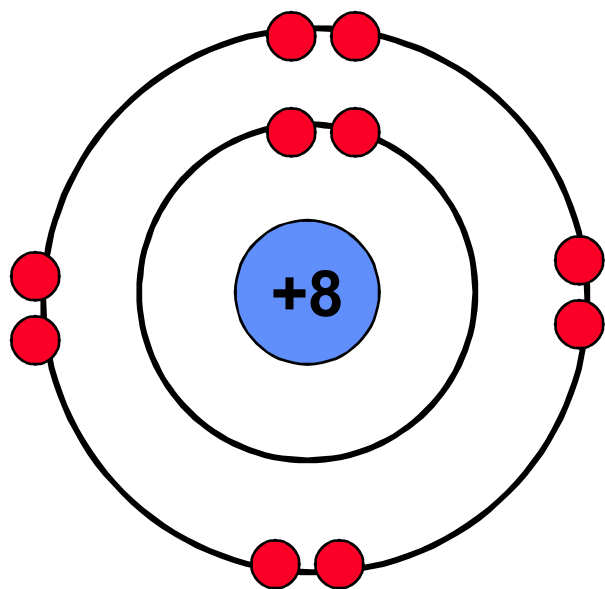


Fe₂O₃

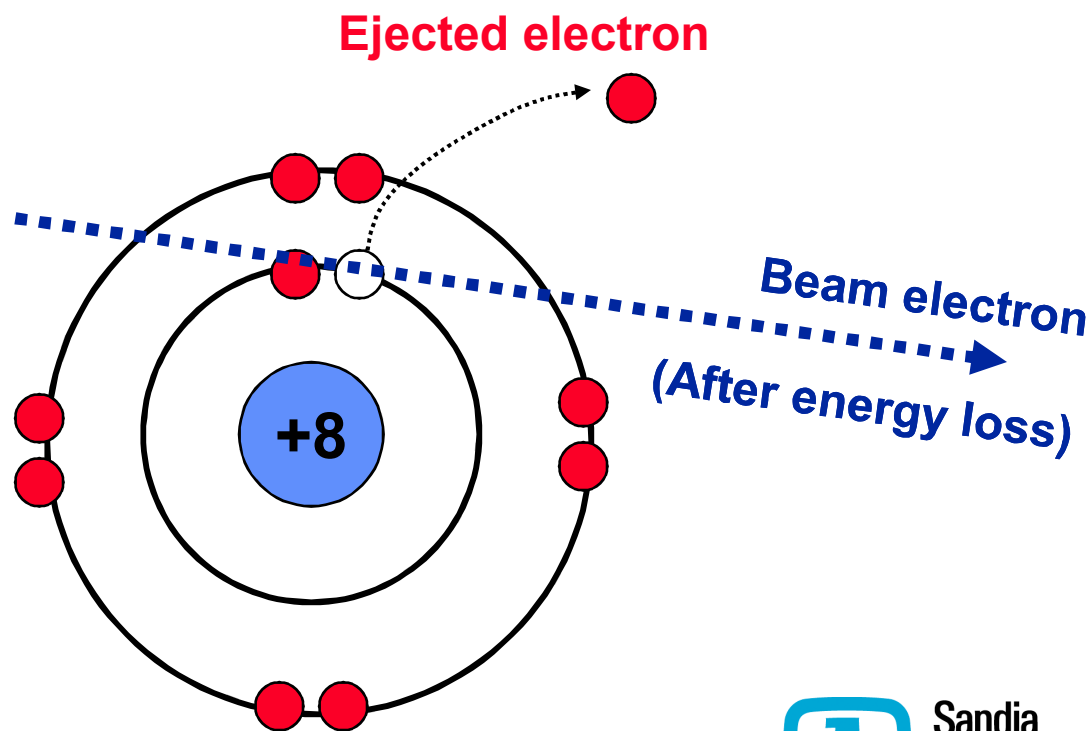
(From Williams
and Carter)

Chemical analysis also possible

An atom in the solid...

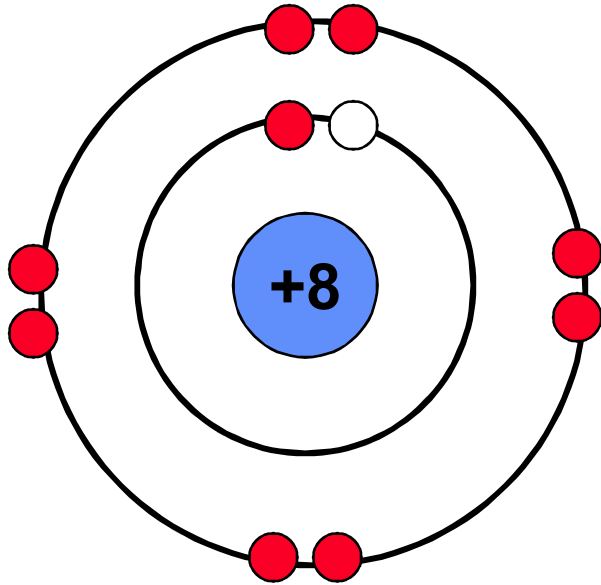


...can have an inner-shell electron ejected by a beam electron

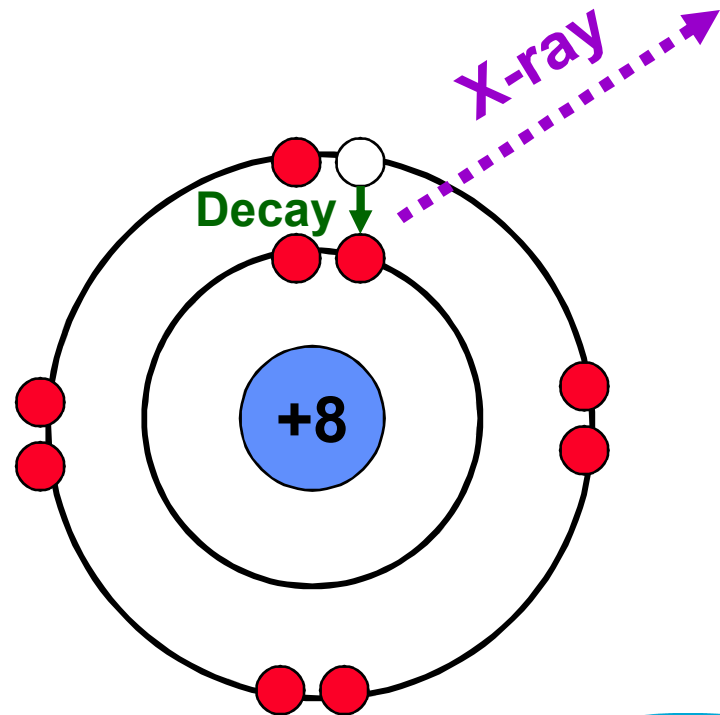


Chemical analysis also possible

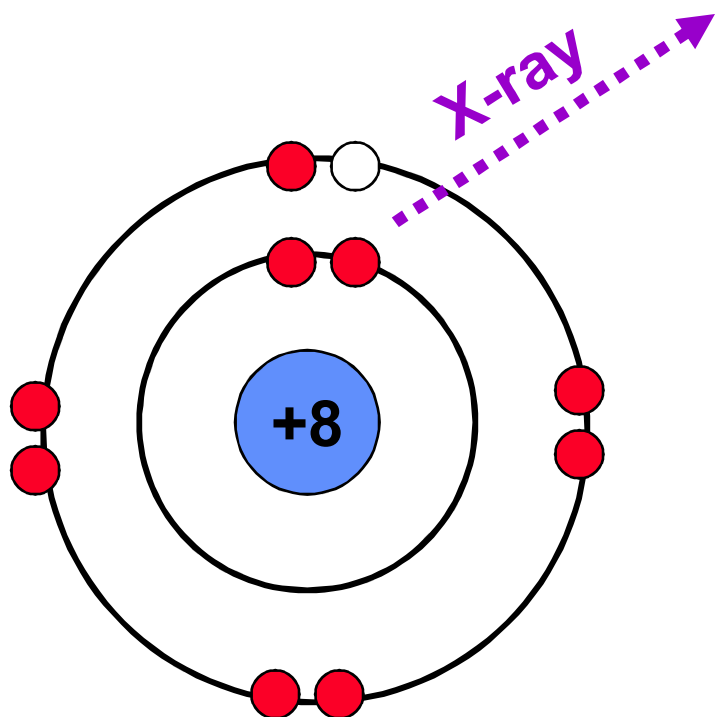
This is unstable...



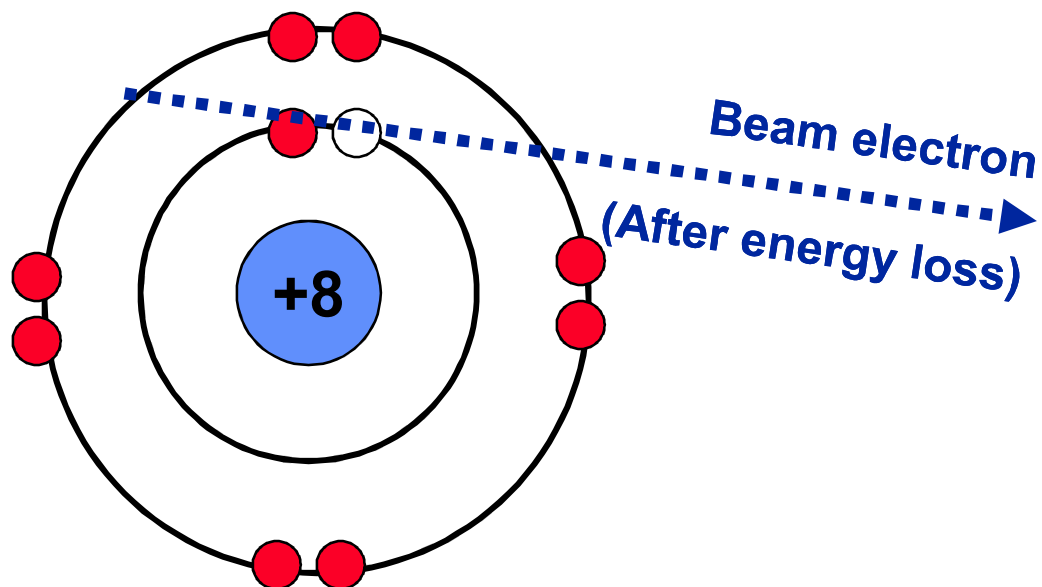
...and may result in X-ray generation



Chemical analysis: two signals to work with

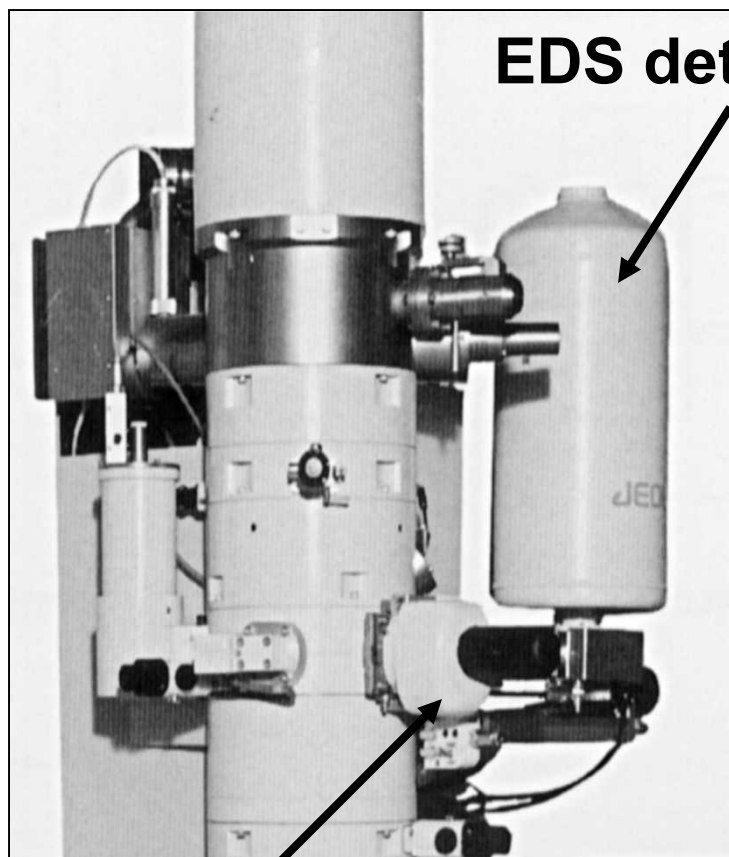


**Energy-dispersive
X-ray spectroscopy:
EDS**



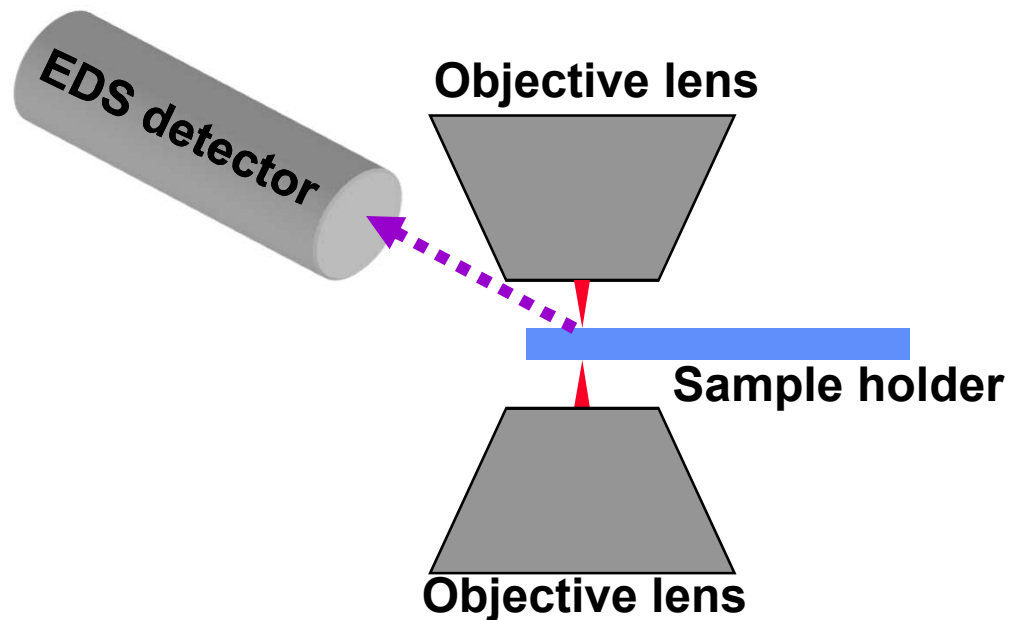
**Electron energy
loss spectroscopy:
EELS**

X-ray spectroscopy



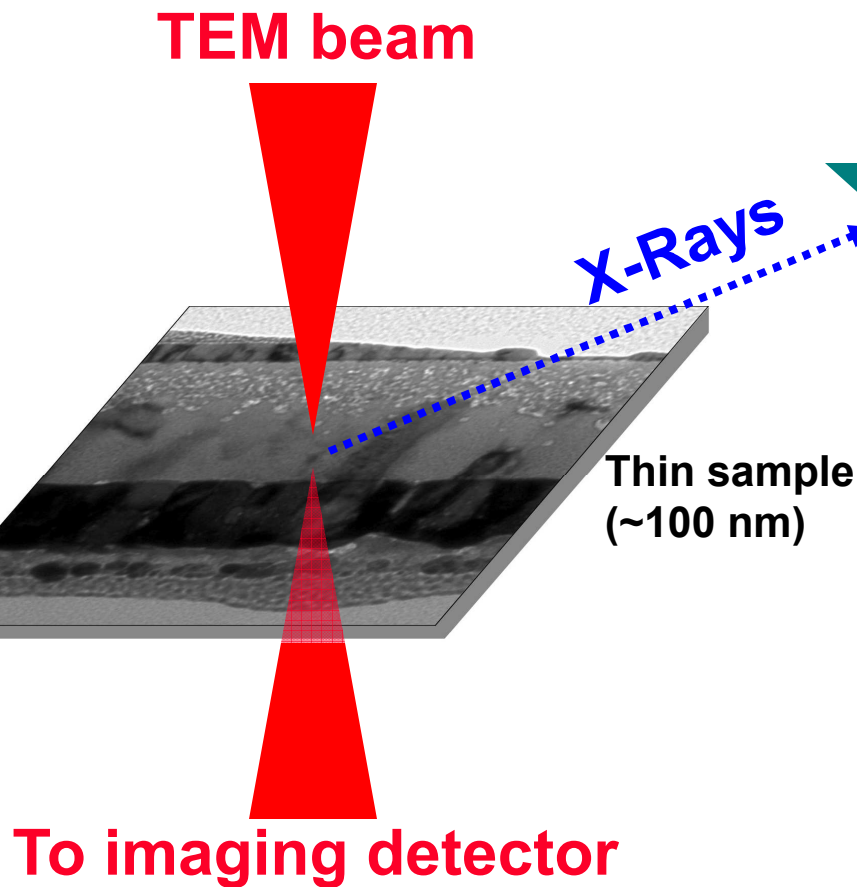
Sample holder

(From Williams
and Carter)



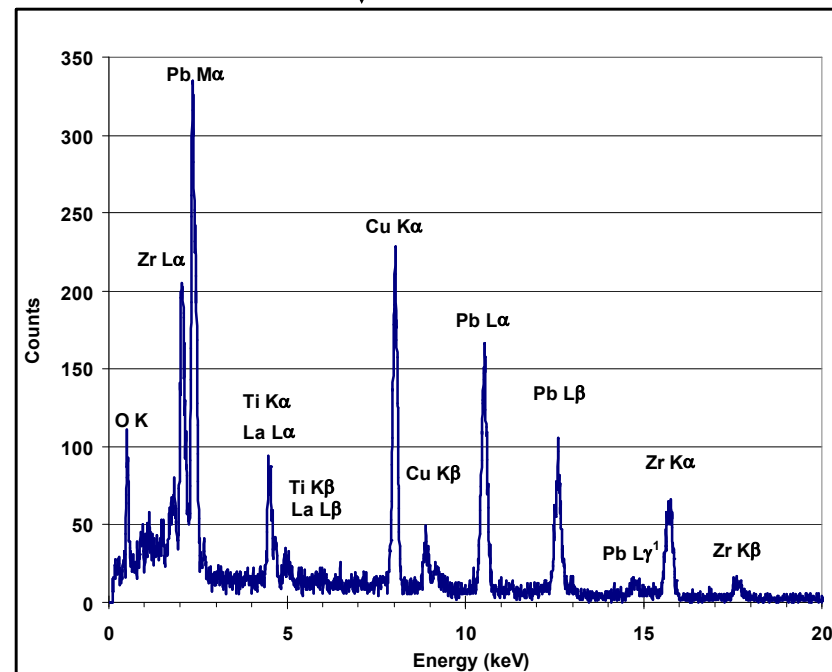
The active area of the detector
must fit inside the objective lens,
along with the sample holder

EDS allows us to qualitatively and quantitatively measure chemistry

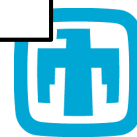
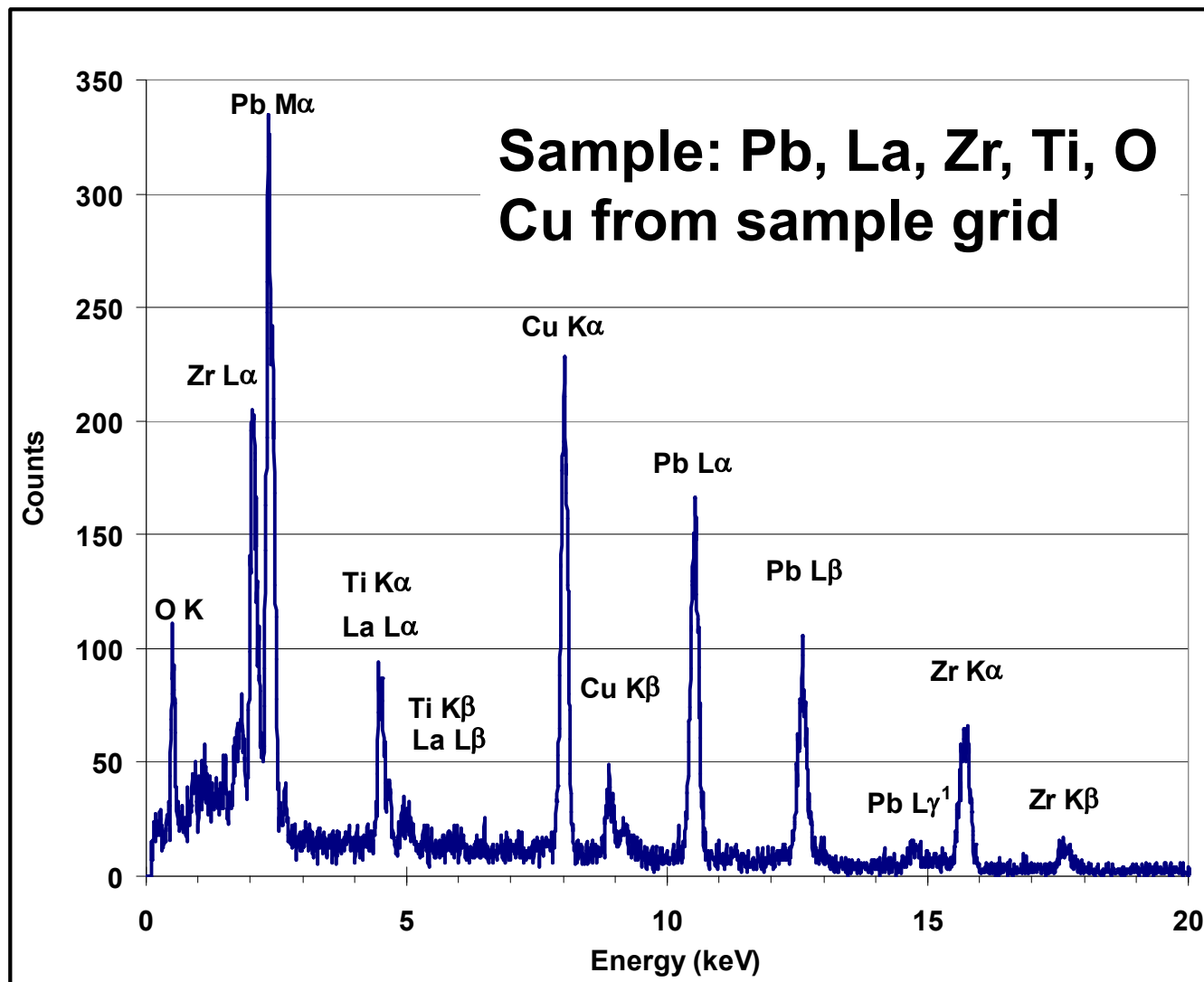


EDS detector

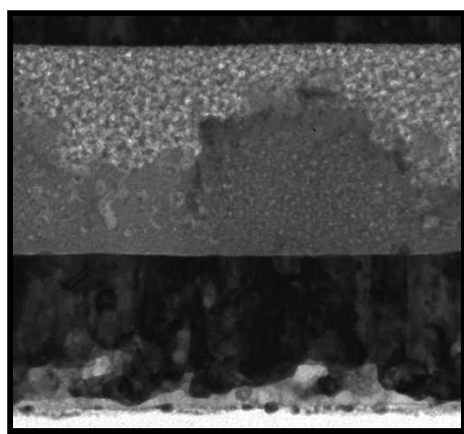
Data



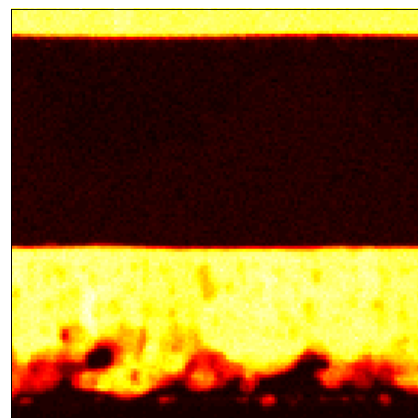
EDS does an excellent job on heavy elements ($\geq \text{Al}$ in modern instruments)



Modern instruments allow mapping of chemistry with \approx few nm resolution

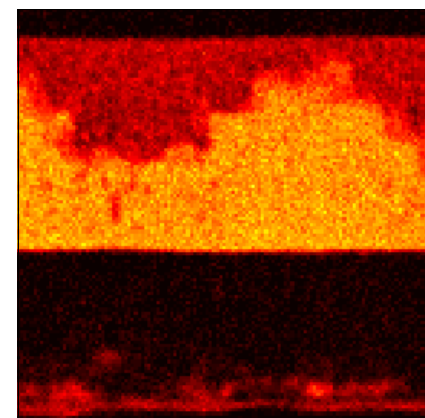


500 nm



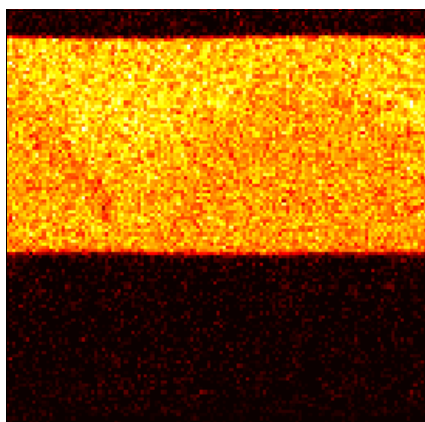
0 100 200 300 400

Pt counts



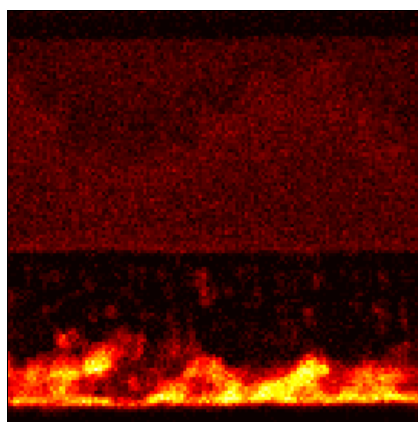
0 50 100 150 200

Pb counts



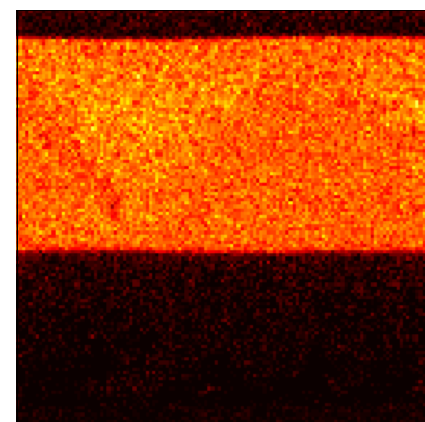
0 10 20 30 40 50 60 70

Zr counts



0 50 100 150 200

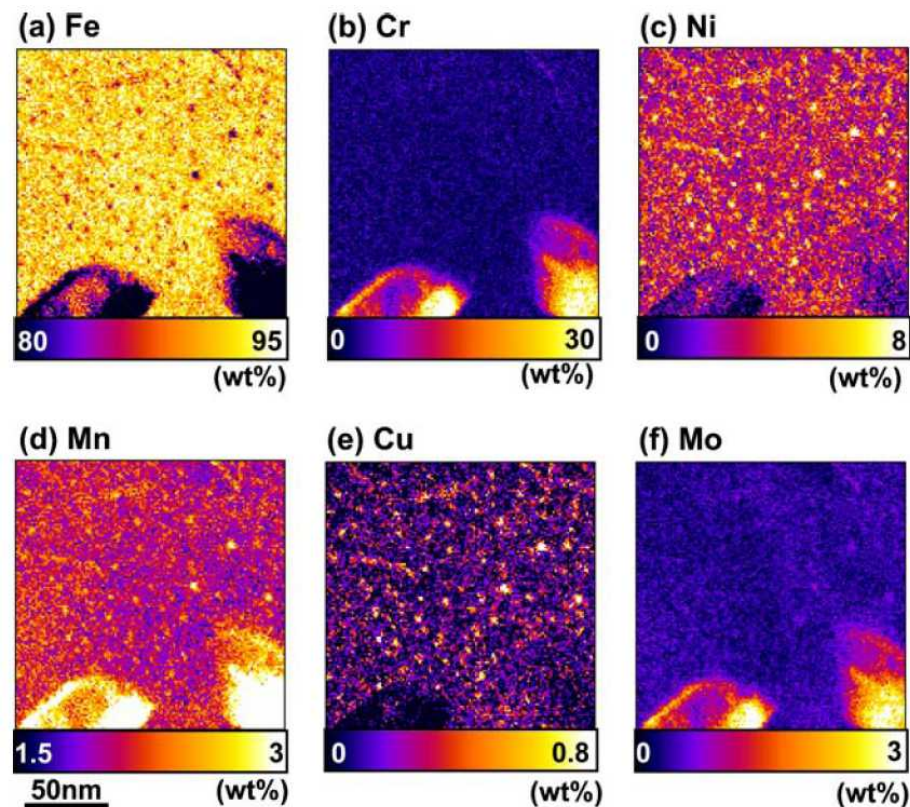
Ti counts



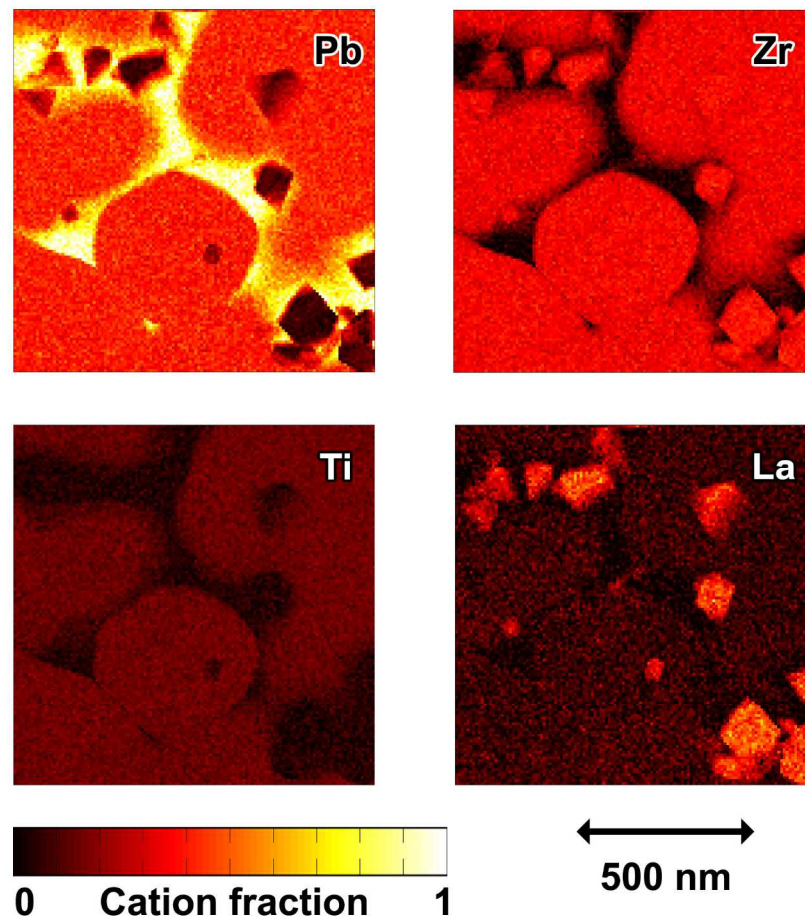
0 5 10 15 20 25 30

La counts

EDS: quantify chemistry at nanometer scale

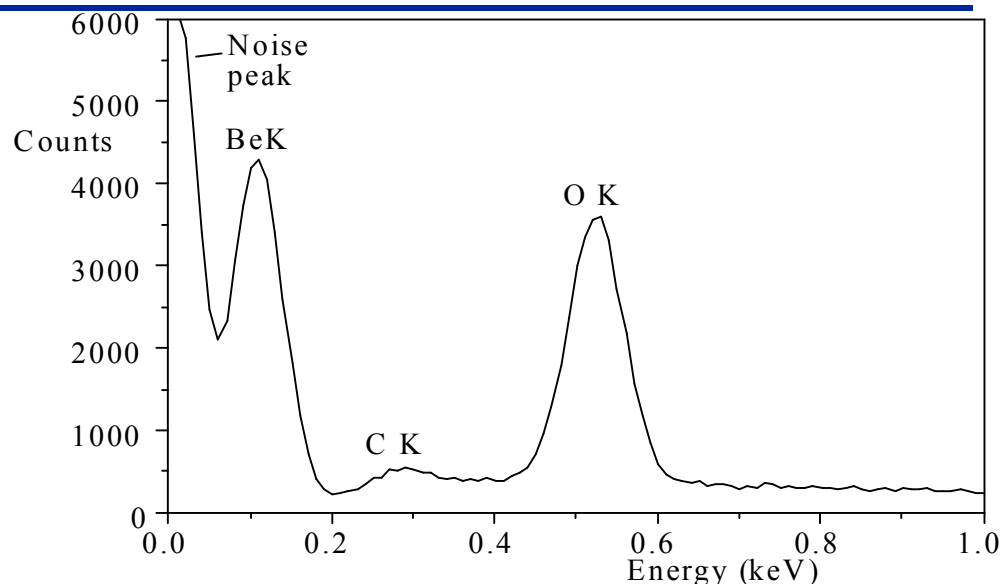


Burke et al., J Mat. Sci.,
V41, P.4512 (2006)



Parish et al., to be
published

Special Consideration for “Light” Elements

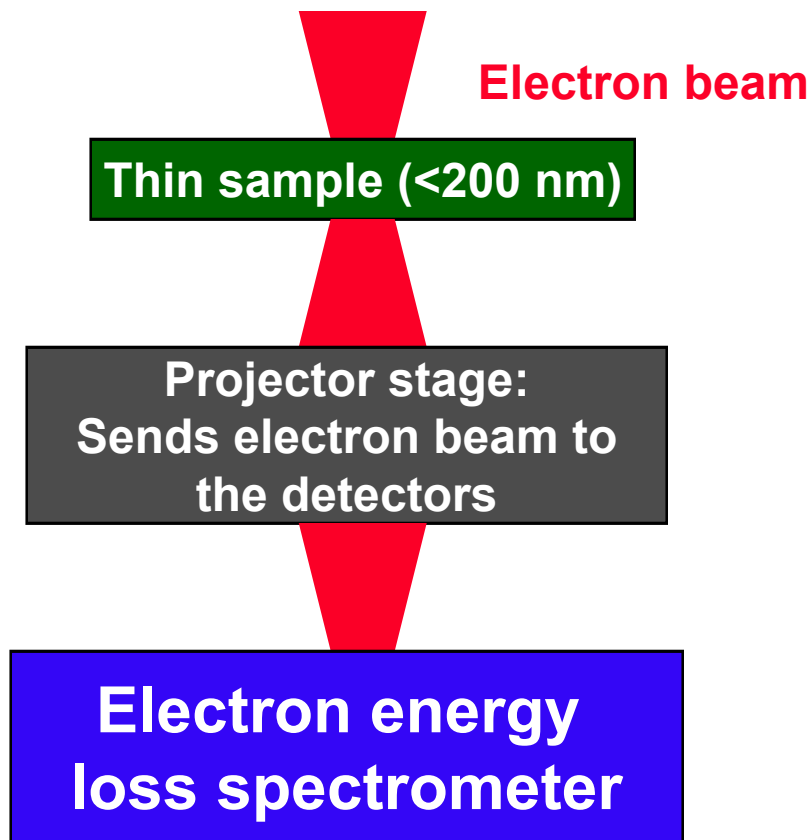
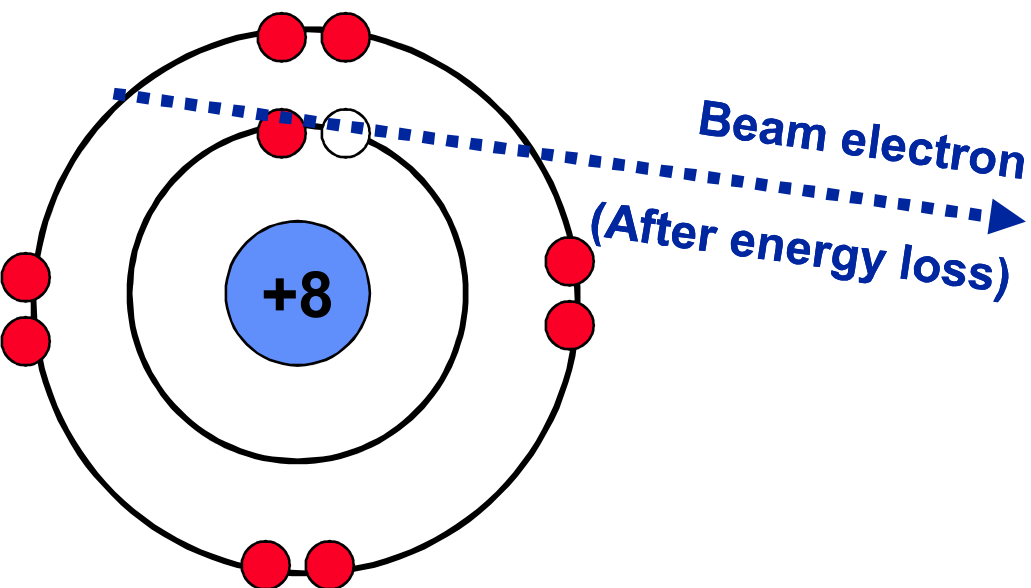


Low Z elements:

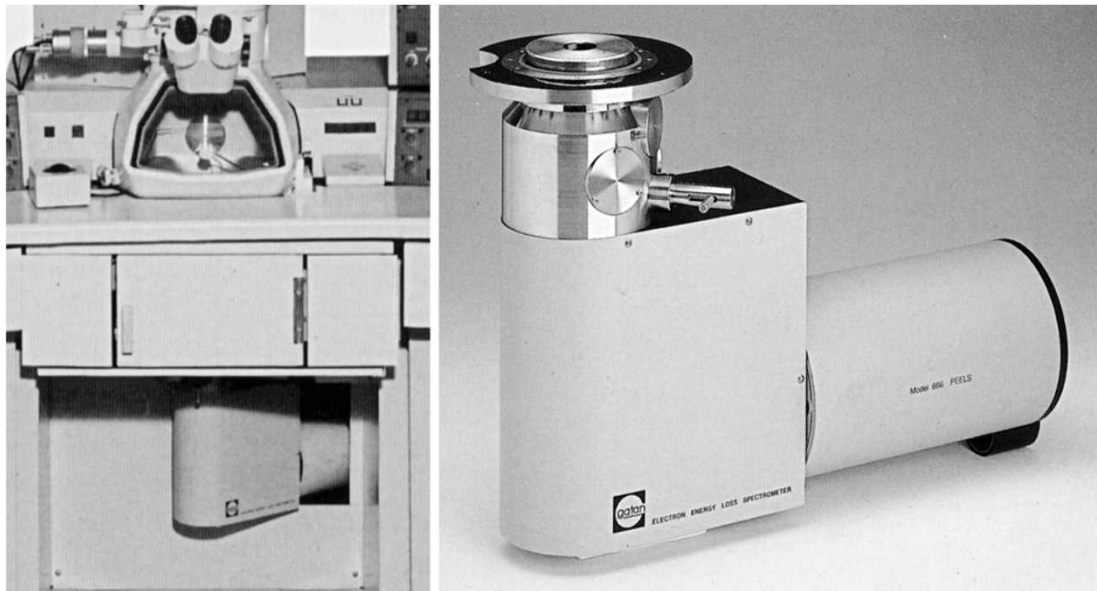
- Don't produce a lot of X-rays
- These X-rays are low in energy and can be readily absorbed
 - By the sample—what's the thickness?
 - By the EDX detector window (Be, ultra-thin polymer, windowless)
- These X-rays are often overlapped with X-rays from higher Z elements (e.g. Cr-L and O-K)
- Also, carbon and oxygen tend to be everywhere—did this signal come from your area of interest?



Electron energy loss spectroscopy



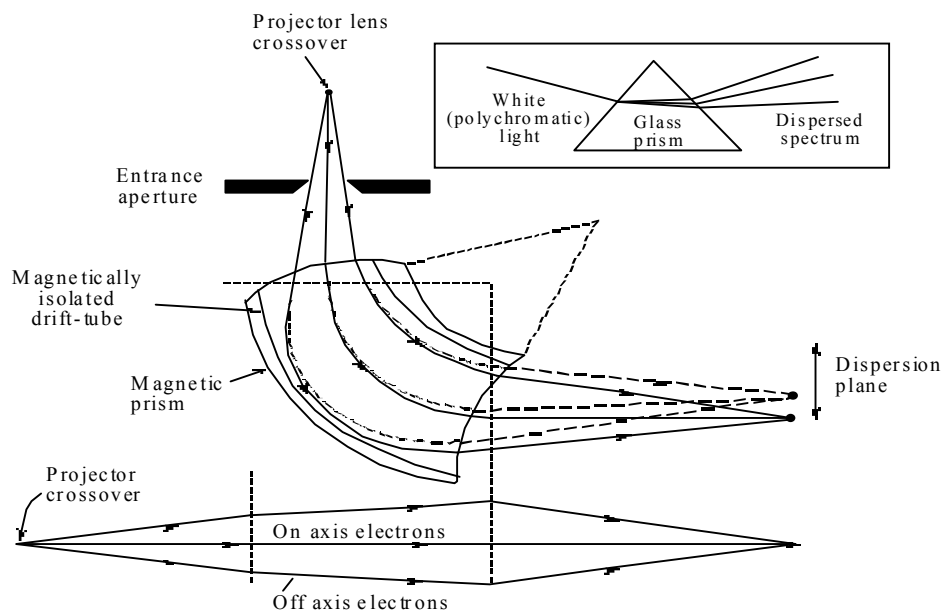
EELS with an Energy Filtered Camera “GIF”



The GIF bolts onto the bottom of the standard TEM column

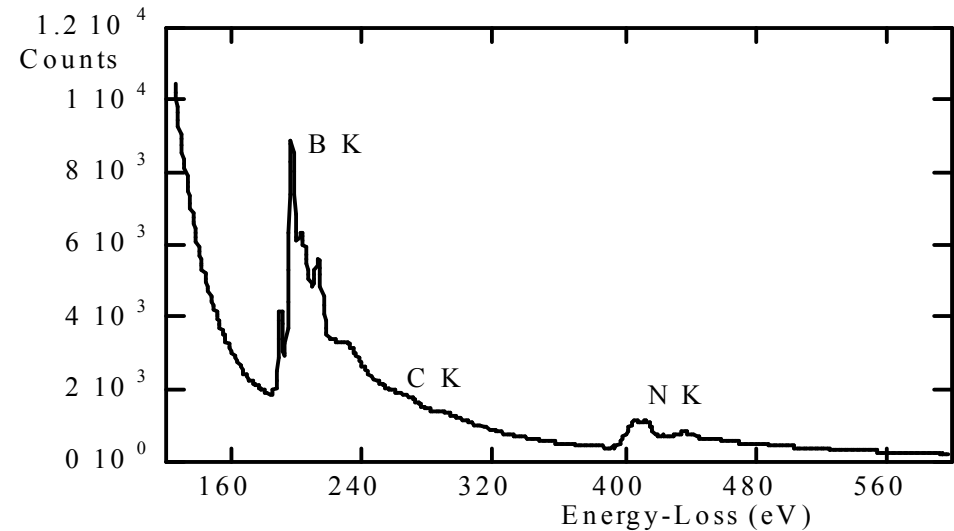
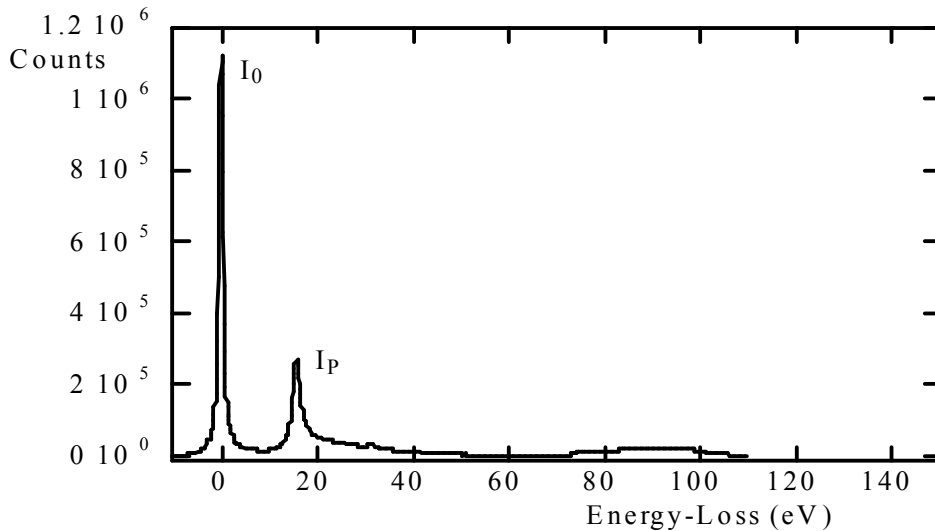
The GIF is a combination of a 90° magnetic prism and a set of lenses.

The “white” transmitted electron beam is dispersed onto a CCD camera as a function of energy.



(From Williams and Carter)

Why do EELS?



Sensitive to light elements

Light elements don't produce a lot of x-rays

The problem with low energy x-ray absorption is gone

Low Z elements produce low loss energy events which are inherently more intense

Can be used for microanalysis

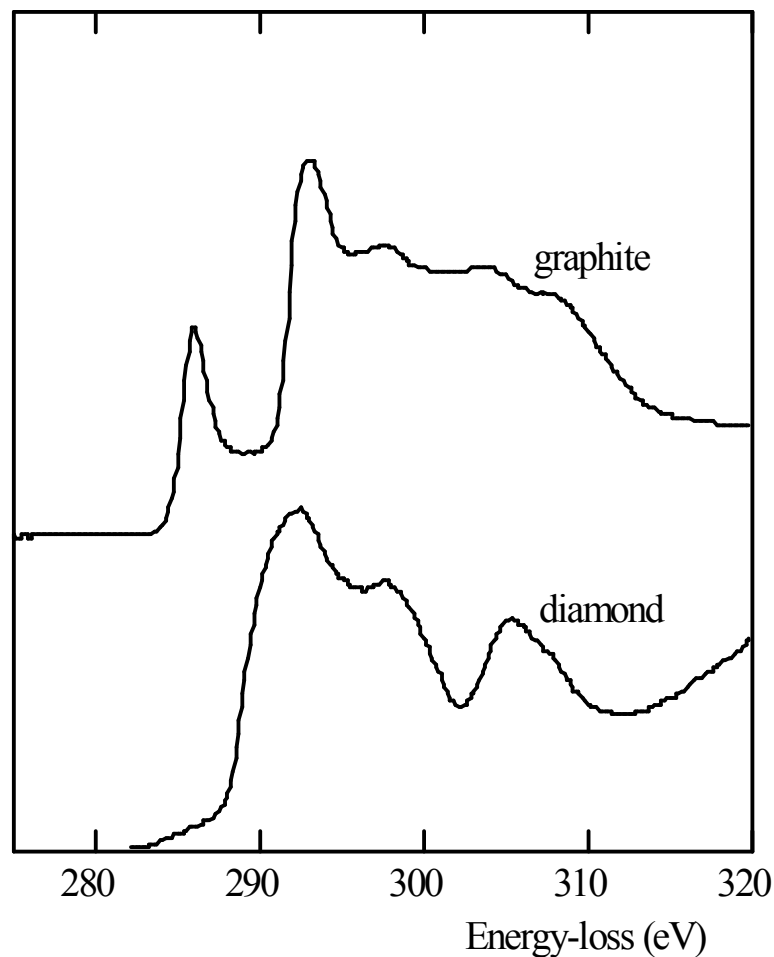
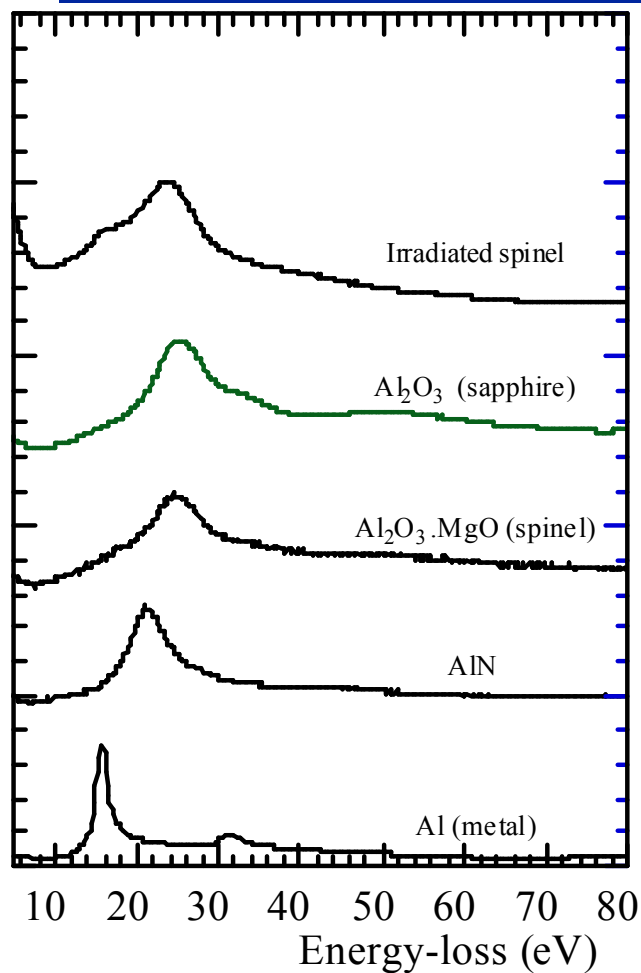
Sensitive to chemical state of materials

Valence measurement

Coordination measurement

(From Williams and Carter)

With EELS, Al is not just “Al”—sensitive to chemical environment



Able to distinguish between graphite
and diamond, carbon isn't just carbon

(From Williams
and Carter)

Compare: EELS to EDS

	EELS	EDS
Identify light elements	Yes	Sometimes
Identify heavy elements	Sometimes	Yes
Quantify light elements	Yes	With effort
Quantify heavy elements	Not very well	Yes
Valence, bonding, local electronic environment	Yes	No
Mapping	Yes	Yes
Best spatial resolution	≈ 0.1 nm	≈ 1 -2 nm
Best spectral resolution	≈ 0.3 eV	≥ 100 eV
Typical spectral range	0-2 keV	.1-20 keV
Artifacts	Many	Many

Summary: TEM

TEM allows imaging, crystallography, and analysis at the nanometer scale

TEMs cost millions of dollars – use TEM when SEM, XRD, etc., are too coarse to answer your question

Many signals can be measured from the same sample area – synergistic information

Sample preparation is the slowest and most difficult step